

CONNECT  
COLLABORATE  
CREATE



# NSF Workshop on Research Education and Workforce Development

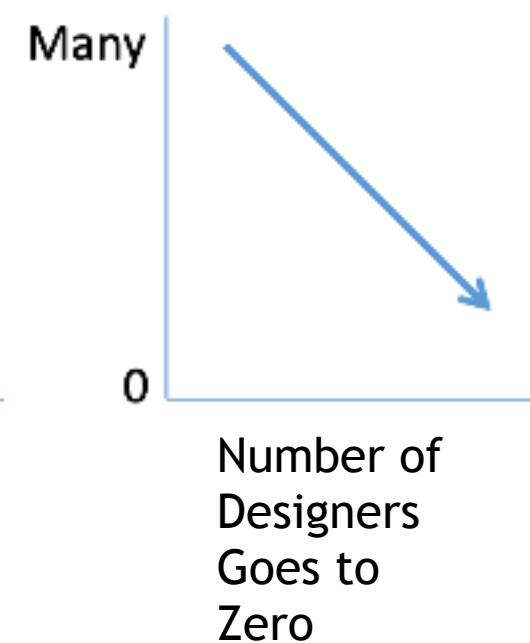
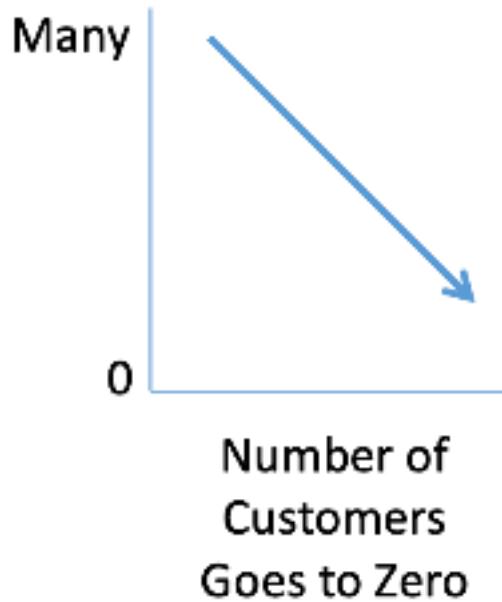
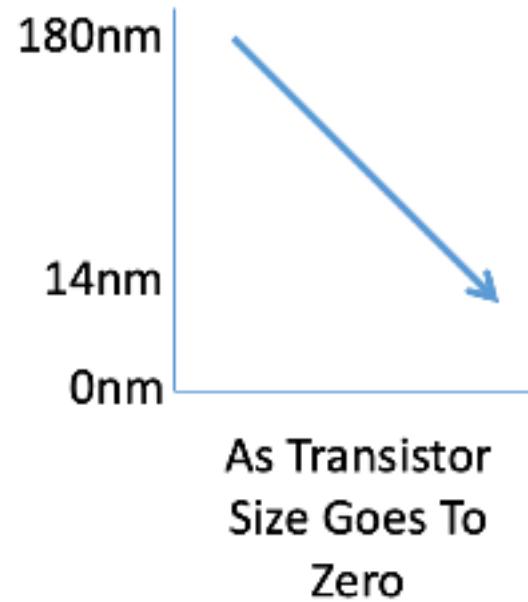
October 14/15, 2021

Mohamed Kassem

Cofounder & CTO, EFABLESS.COM

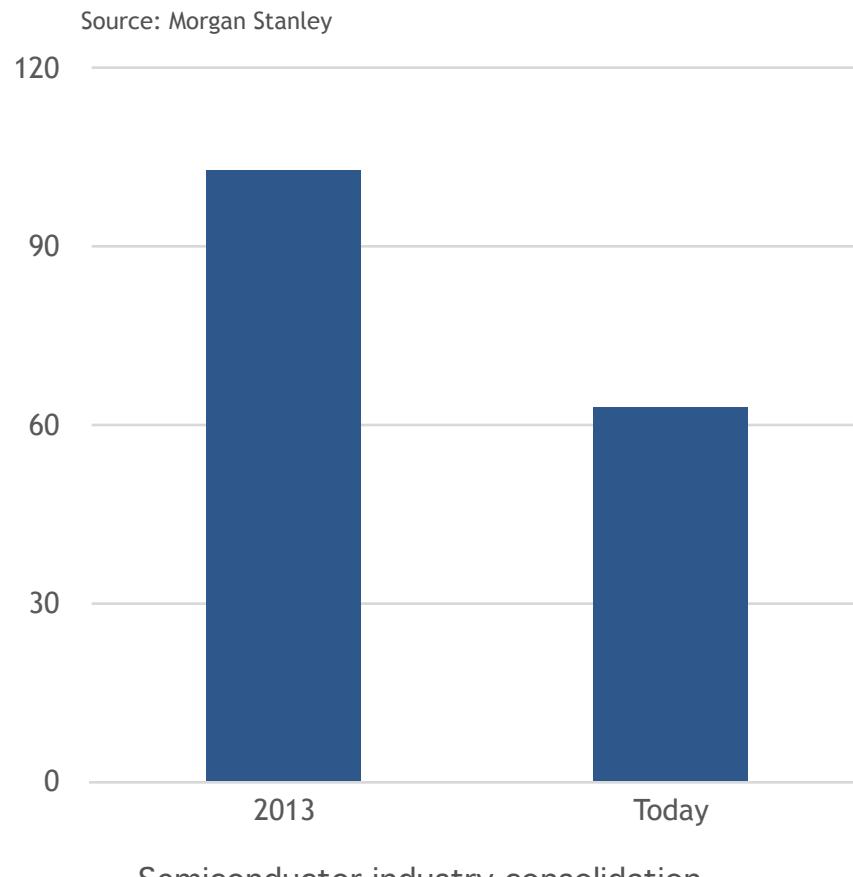
[mkk@efabless.com](mailto:mkk@efabless.com)

# CHALLENGING INDUSTRY TRENDS

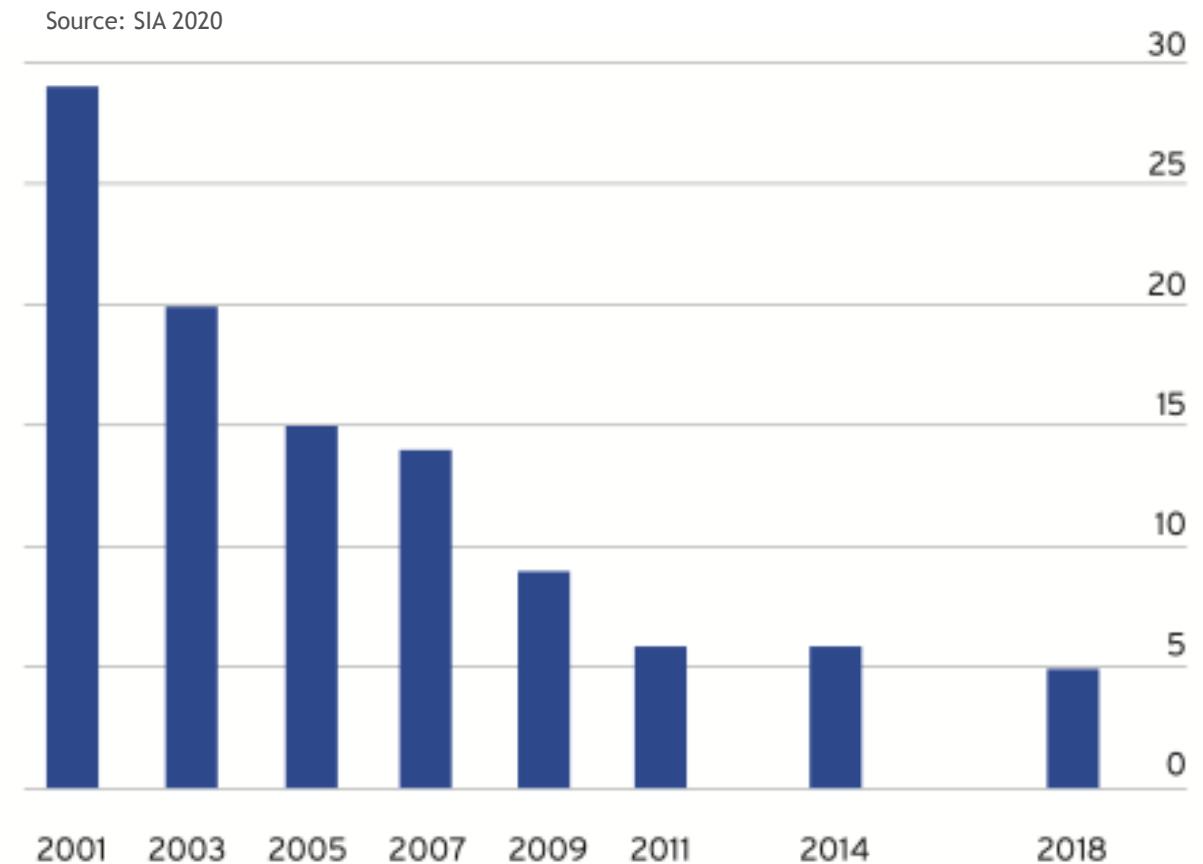


Source: Mike Noonan

# INDUSTRY DYNAMICS



**Semi Companies Larger Than \$100M**



**Semi Companies Delivering Lead-in Edge Tech**

# THE FUTURE - THE DESIGN GAP

Markets Served  
By Traditional  
Methodology



# THE TALENT GAP

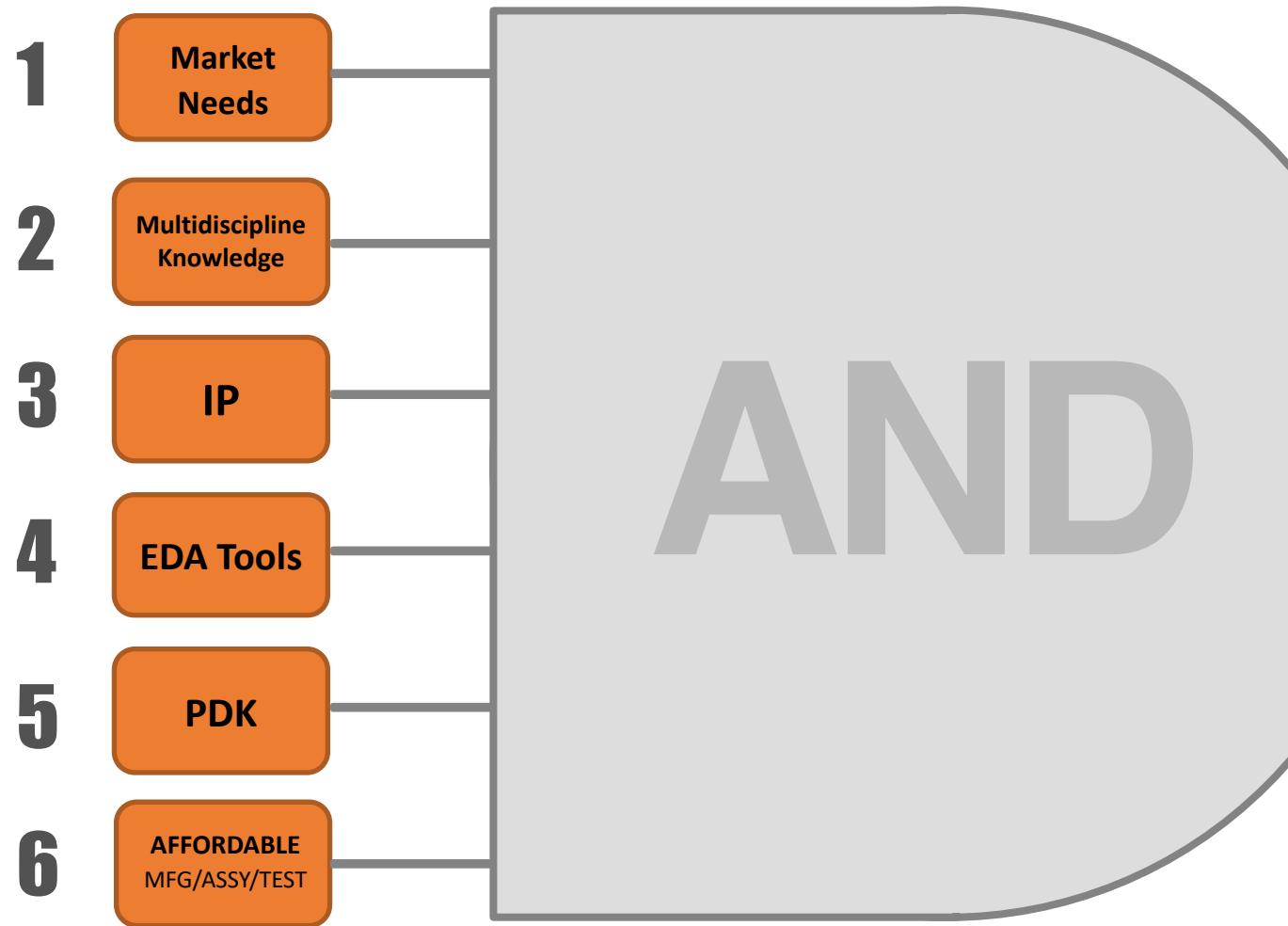
*Is the industry concerned about innovation in semiconductors & its applications? .... Yes!*



John Neuffer, CEO of SIA, at GlobalFoundries GTC2020 Forum

# CURRENT CHALLENGES

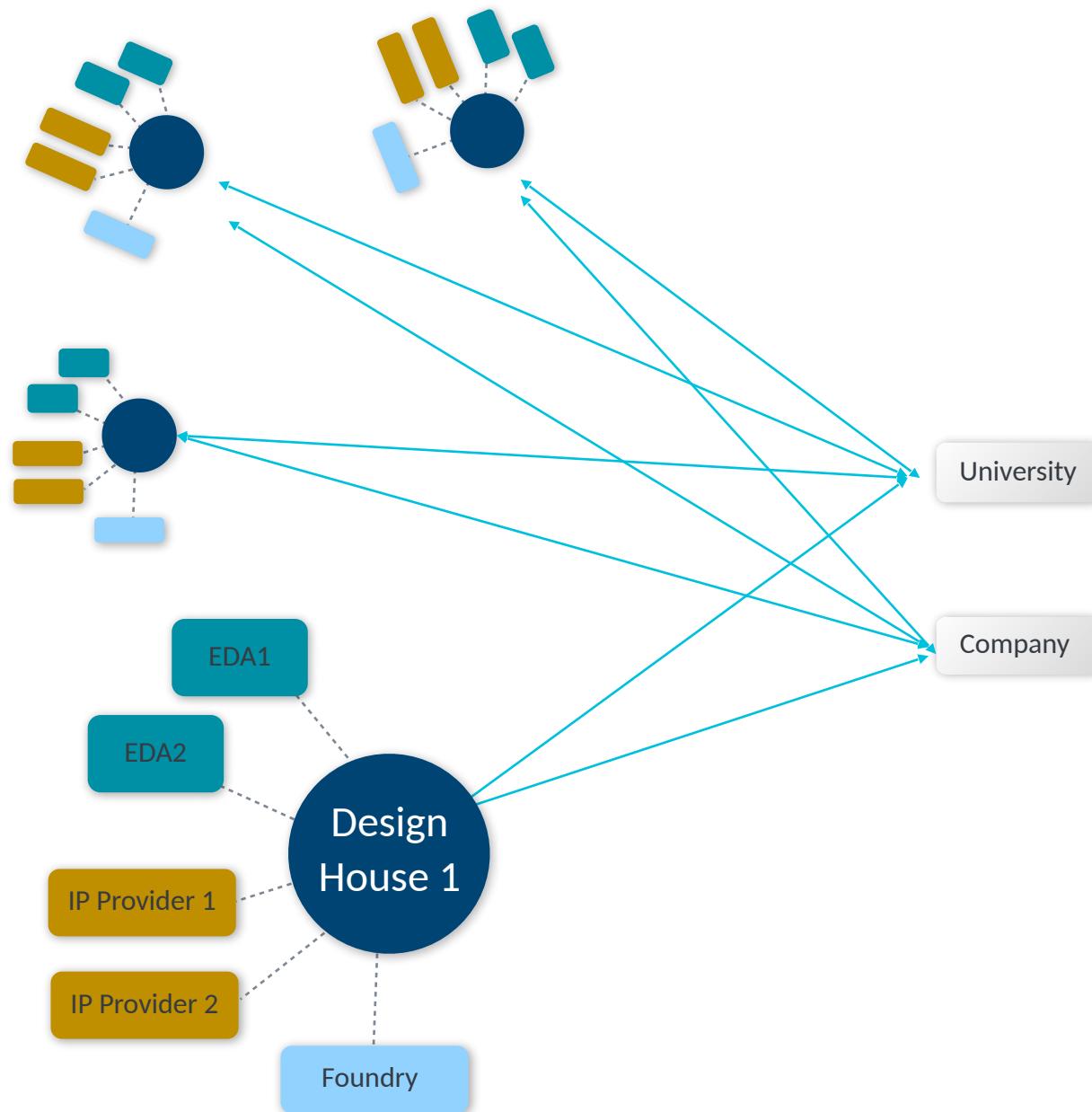
# IT'S AN AND GATE



Real life application

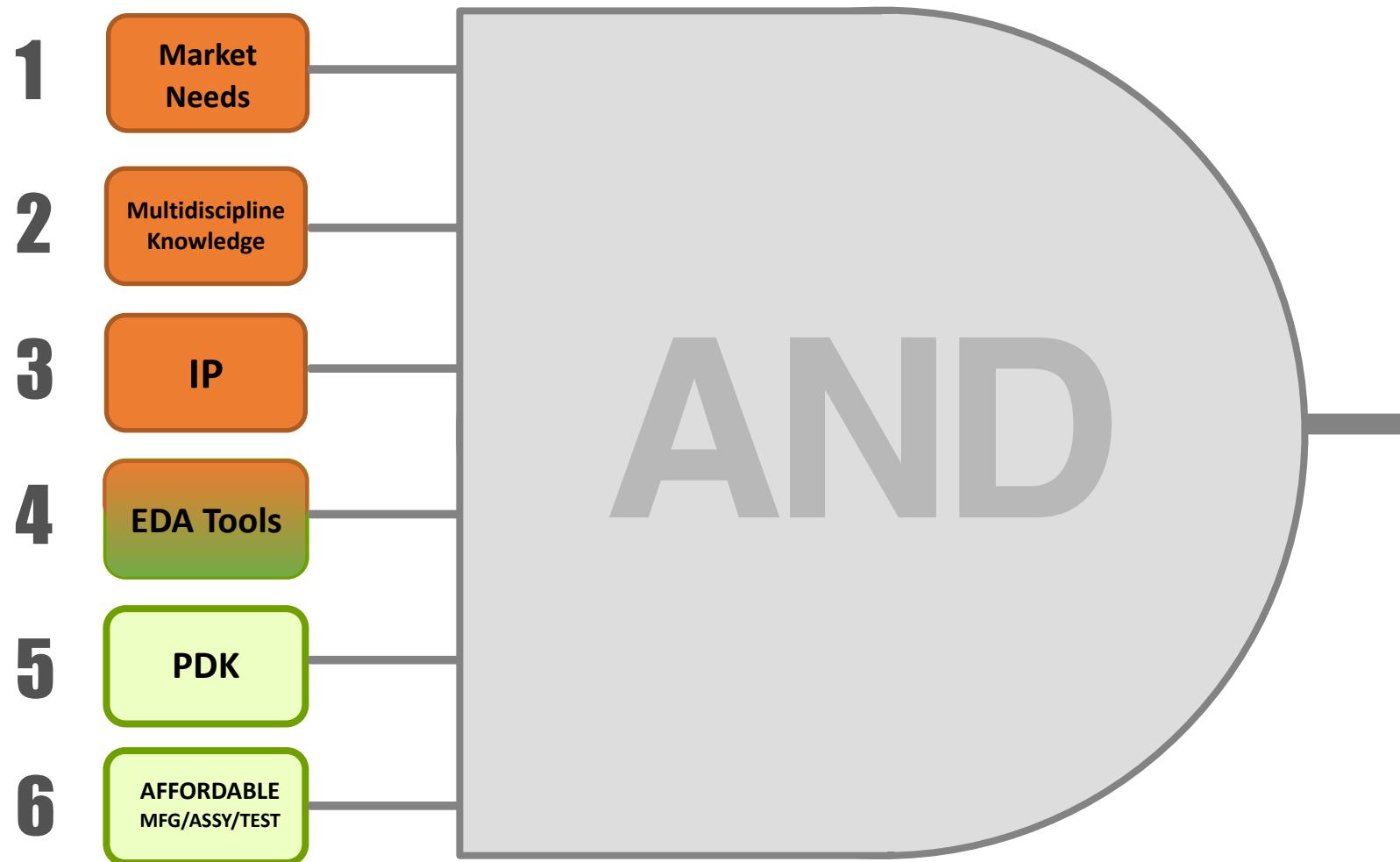


# TODAY'S APPROACH



Every design entity needs  
to establish **independent**  
business and contractual  
(including NDA's)  
relationships with **multiple**  
IP providers, EDA vendors,  
and foundries

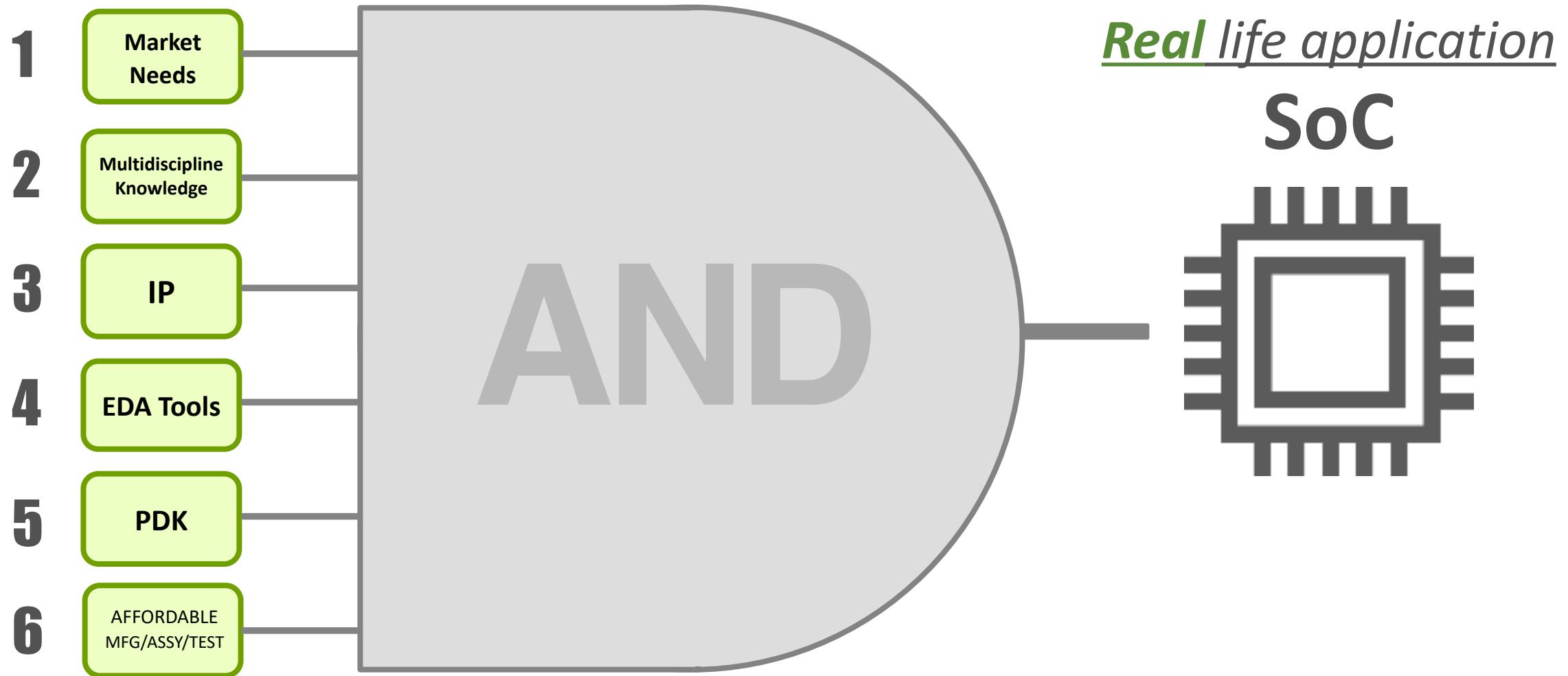
# PARTIAL SOLUTIONS FAIL



Real life application



# MUST CREATE NO COMPROMISE CHANGE



# GOV'T SUPPORT EXAMPLE



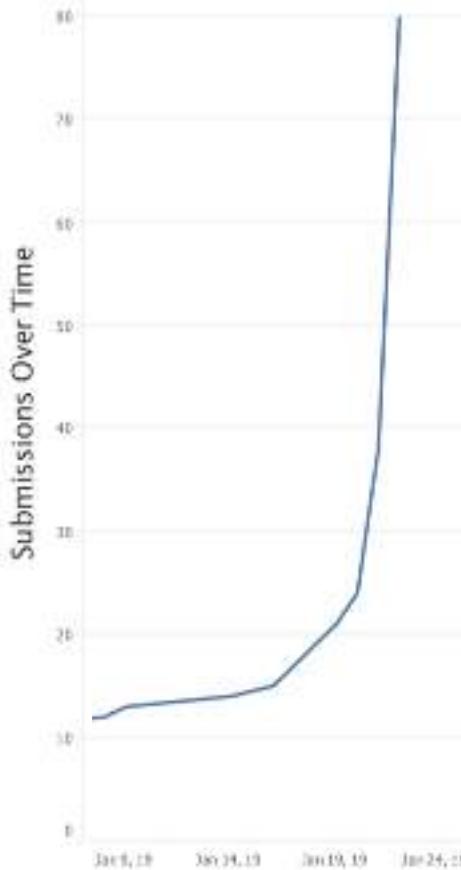
## AFRL's Advanced Microelectronics Design & Prototype Challenge

What is your solution for a **14/12nm** advanced SoC that can operate and improve the features of an **autonomous** product of your choosing while **maintaining** the **integrity** (provenance, traceability) and **security** needs (information protection, mathematical algorithms) of critical systems?

# ME CHALLENGE STATS



Total Submissions  
by Date



**82**

TOTAL  
SUBMISSIONS

**45**

SHOWCASE  
INVITEES

**12**

PHASE1  
FINALISTS

**3**

PHASE2  
FINALISTS

[Link to the Proposals](#)

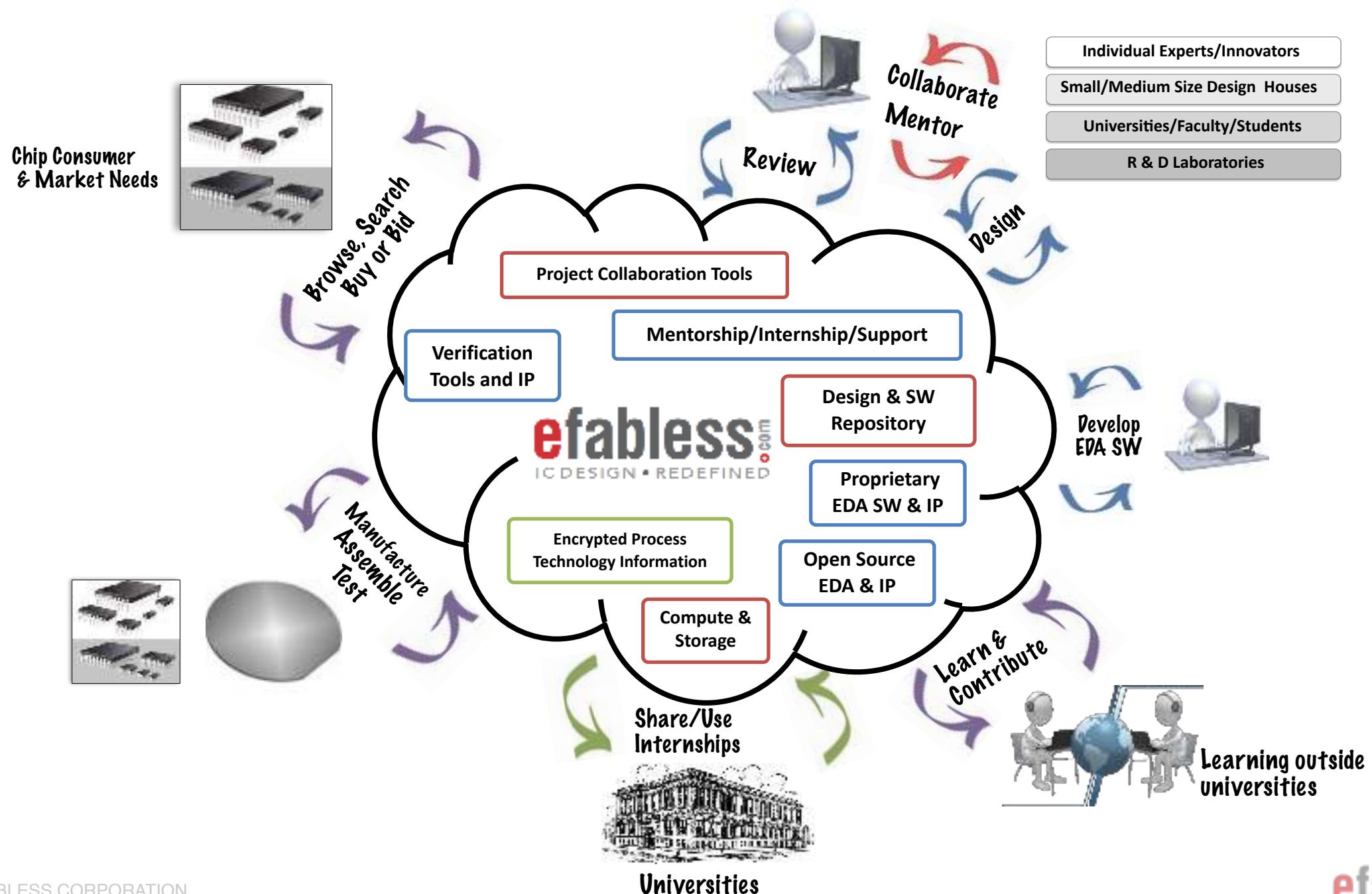
<https://drive.google.com/drive/folders/1lyVPkLx1vpWcK8R-KJlgX42zdbRSeBBh?usp=sharing>

# AFRL CHALLENGE – KEY OBSERVATIONS

- **No shortage of ideas / target applications**
- When you eliminate the barriers - **Talent shows up**
- **Size ranges from 2-person to 50+ person entities**
- Many of the performers newly exposed to 12nm node
- Because it was public - **facilitated collaboration work**
- 7-month delay dose of licensing & contractual gates

# WHAT EFABLESS DOES

**simplify Chip creation** and  
**open it to everyone**



# CLOUD - BUT NOT FOR COMPUTE

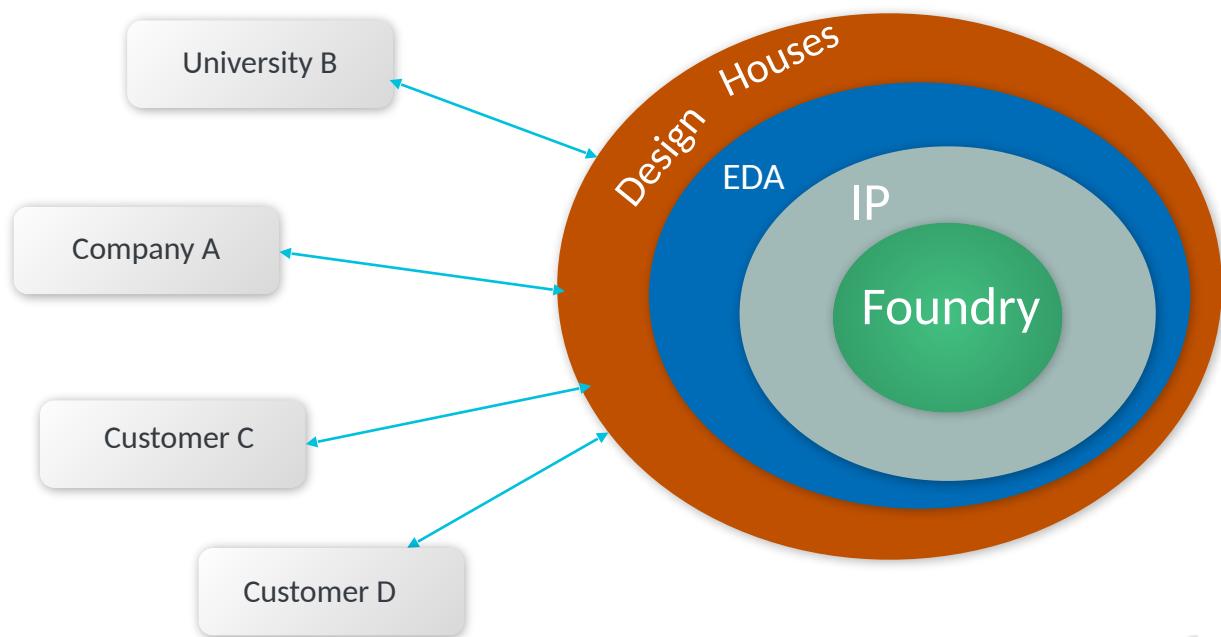
Secure, cloud-based platforms, all the resources and processes required to design ASICs and IP are offered in one place while maintaining the “fire-walling” of IP information and with enhanced traceability and on-demand elasticity.

Enabling a worldwide network of developers and customers to collaborate, model, and verify custom SoCs. When custom SoC creation becomes less risky and more cost-effective, innovation is unleashed.

Scalable & elastic design/development capacity

Facilitates Collaboration, reference designs and design re-use accelerates development and reducing costs

Risk reward sharing enabled by consolidated contribution tracking and design obfuscation



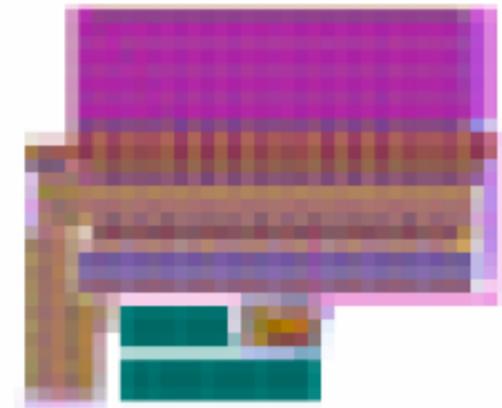
# FOUNDRY DATA OBFUSCATION

Mask-geometry layout is foundry proprietary.

How can you design an entire chip and submit to the foundry for fabrication without signing an NDA, purchasing commercial tools, and installing PDKs?

All analog cells at the transistor level are abstracted views using information from the corresponding LEF files and simulation models

3.3V ADC, Original vendor layout:



(Layout blurred to protect the identity of the victim)

3.3V ADC, Abstracted layout (from LEF view):



Wire to pins  
Obstruction metal layers ensure DRC correct design



# DESIGN IP OBFUSCATION



The target process: **X-FAB XH018**

Base MOS LP (low power) option

6 metal stack (5 standard route layers, 1 thicker top)

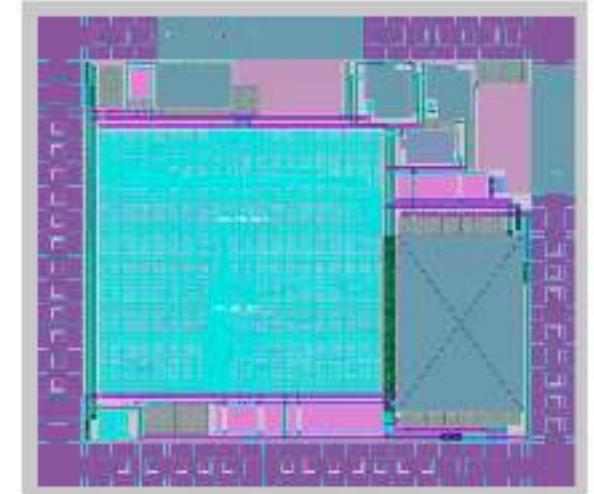
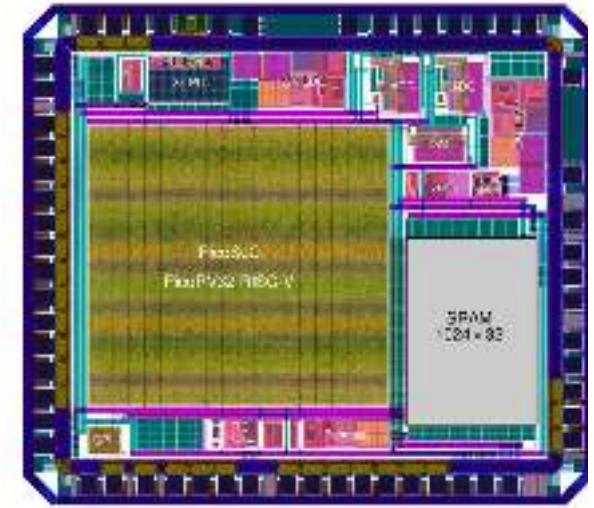
The proprietary data:

X-FAB digital standard cells

X-FAB I/O Cells(3.3V with both 3.3V and 1.8V core)

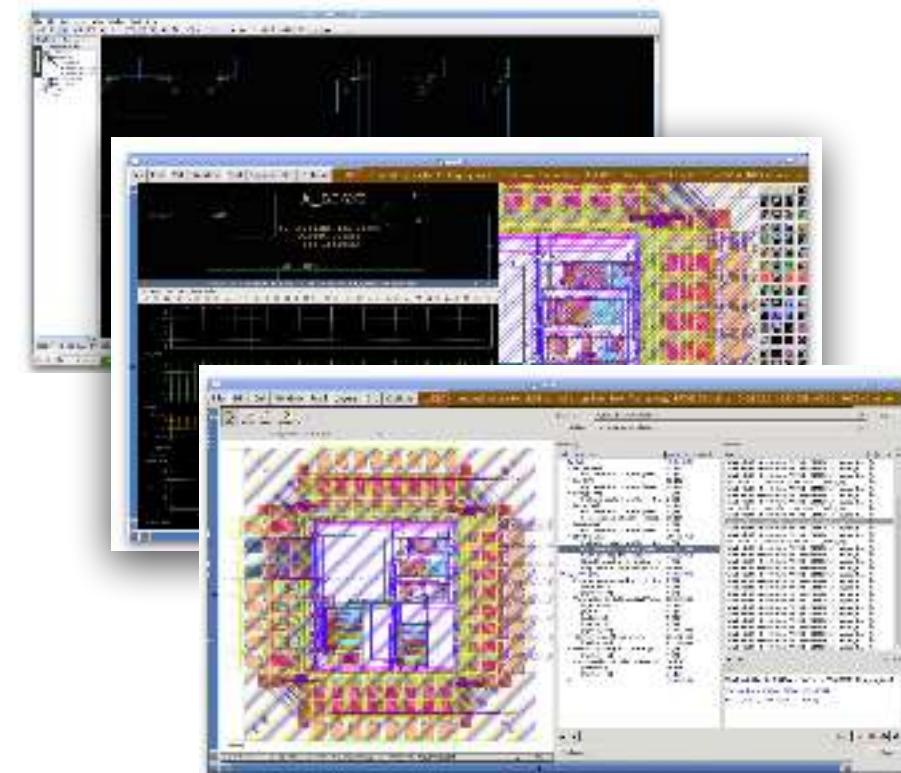
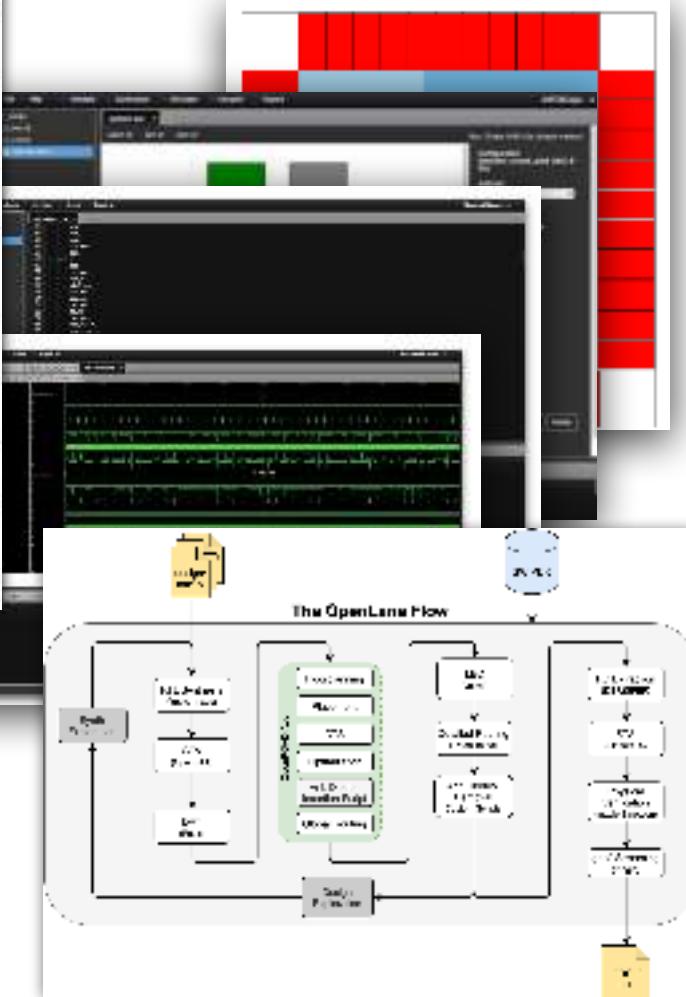
X-FAB Analog IP

X-FAB SRAM (from memory compiler)



# OPEN SoC DESIGN FLOWS & TOOLS

DESIGN STEP	QFlow	CloudV SoC	OpenLane
System Design	N/A	CloudV	CloudV
RTL Lint	Venilator	Venilator	Venilator
RTL Simulation	Verilog	Verilog	Verilog
Logic Synthesis	Yosys	Yosys	Yosys
DFT Scan Insertion	none	none	Parcell
DFT ATPG	none	none	Bault
Formal Verification	none	none	none
Placement	graywolf	graywolf	OpenROAD
Routing	grouter	grouter	OpenROAD
CIS	QFlow	QFlow	efabless CIS
Dynamic EMIR	none	none	none
Extraction	Magic	Magic	Magic
Timing Analysis	Netgen	Netgen	OpenSTA
Floorplanning	Magic	efloorplan	OpenROAD
Top-Level Placement	Magic	efloorplan	efloorplan
Top-Level Routing	Magic	Magic	OpenROAD
LVS	Neogen	Neogen	Neogen
DRC	Magic	Magic	Magic
CDS	Magic	Magic	Magic
SAC	Raven	Raptor	StarRC



- SoC Editor
- RTL Simulation
- Synthesis
- GL Simulation

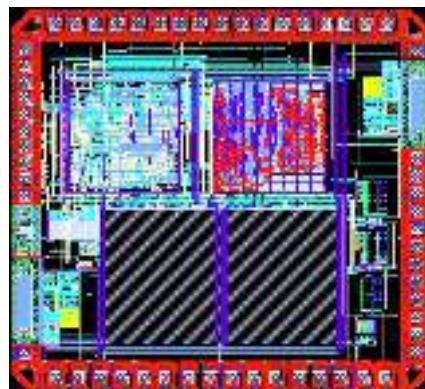
**OpenROAD**  
**OpenLane**

- Schematic Capture
- Mixed-Mode Simulation
- SPICE Simulation
- Parasitic Extraction
- Physical Verification

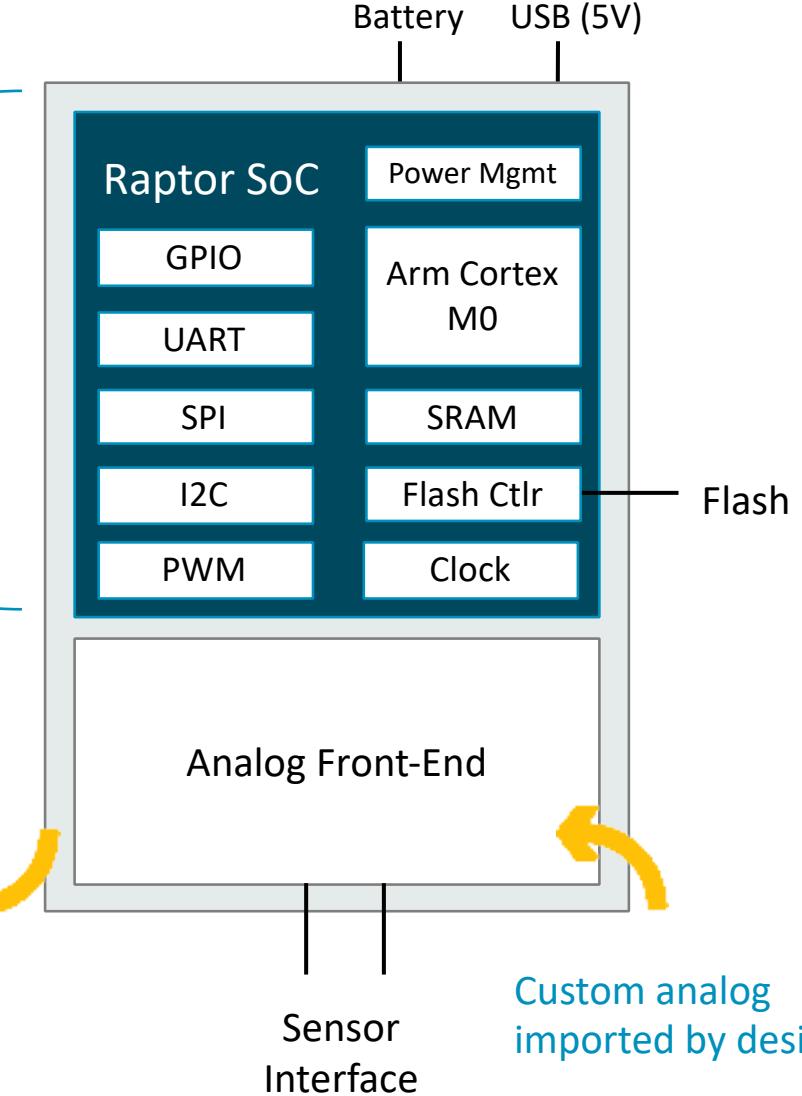
# PROPRIETARY EDA TOOLS

## SIEMENS EDA

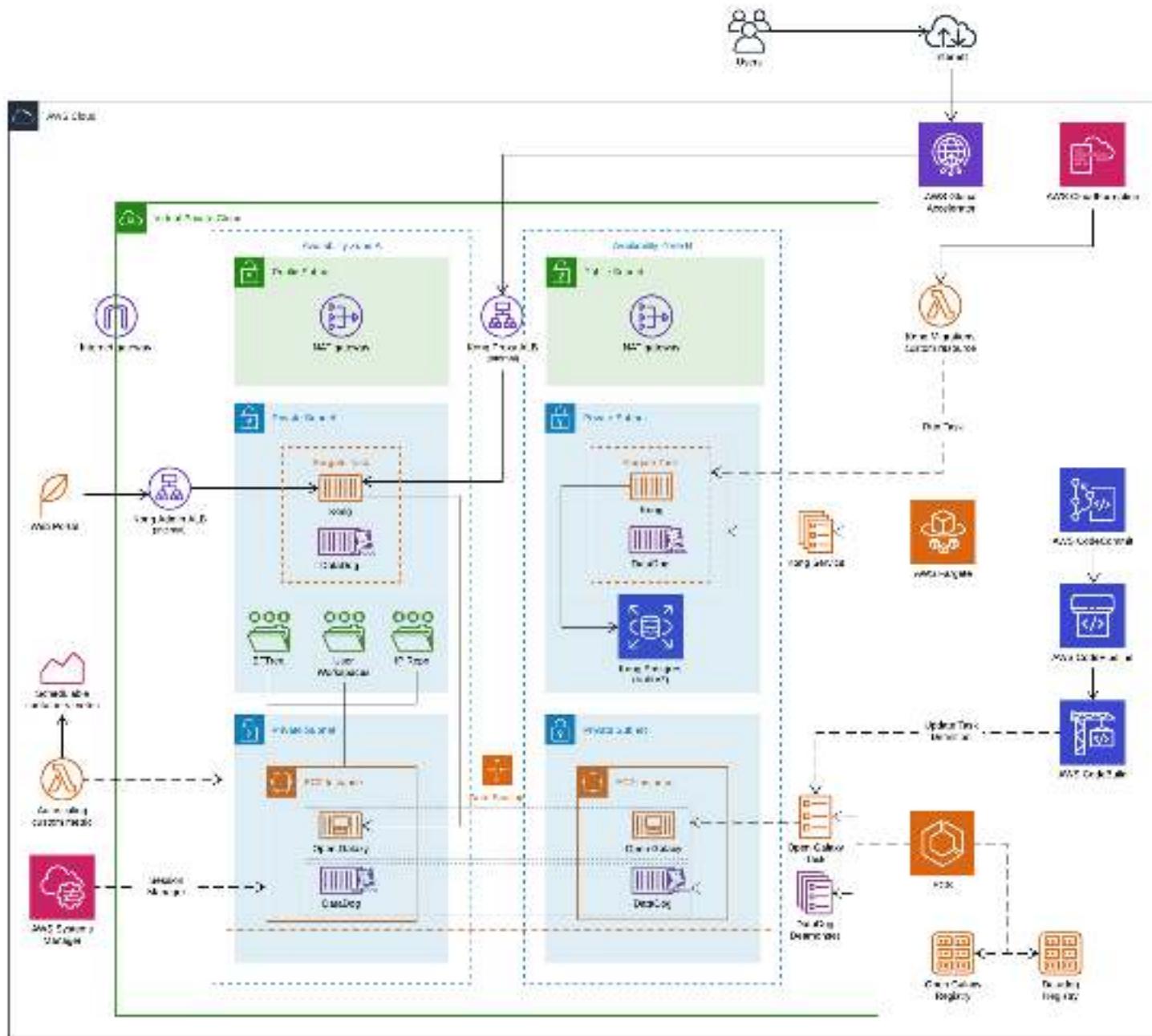
- Seamless integration in **efabless** platform
- Complete Mentor/Tanner design flows
- Process technology support 65 through 22FDX
- Optimized SoC template implementation



Generated  
thru SoC  
design  
template



# CLOUD “WARE”



- Modern
- Secure
- Access control
- Scalable
- Containerized
- AWS (+ awsgov)
- Analytics / traceability

# KEY PLATFORM FEATURES

- Instant access to the platform - less than 5 minutes
- Option for No-NDA Access To Foundry Process Technology - efabless' obfuscation technology
- No Upfront Cost Microelectronics Design Tools (EDA) using proven Open Source & Proprietary SW
- No IP licensing cost for prototyping enabled by IP obfuscation
- No cost Try Before Use/Buy for proprietary designs while protecting IP information and ownership
- Low cost prototype manufacturing options as multi-project-wafers (MPW) including bench setup
- Built-in project collaboration, forums and management enabling effective knowledge exchange
- Provides results-based reputation/certification indicators based on real user design performance
- Supports online project-based - design, verification & validation of microelectronics
- Elastic and scalable infrastructure to support 10,000's of users
- Marketplace connecting designers to potential customers for their unique design innovation

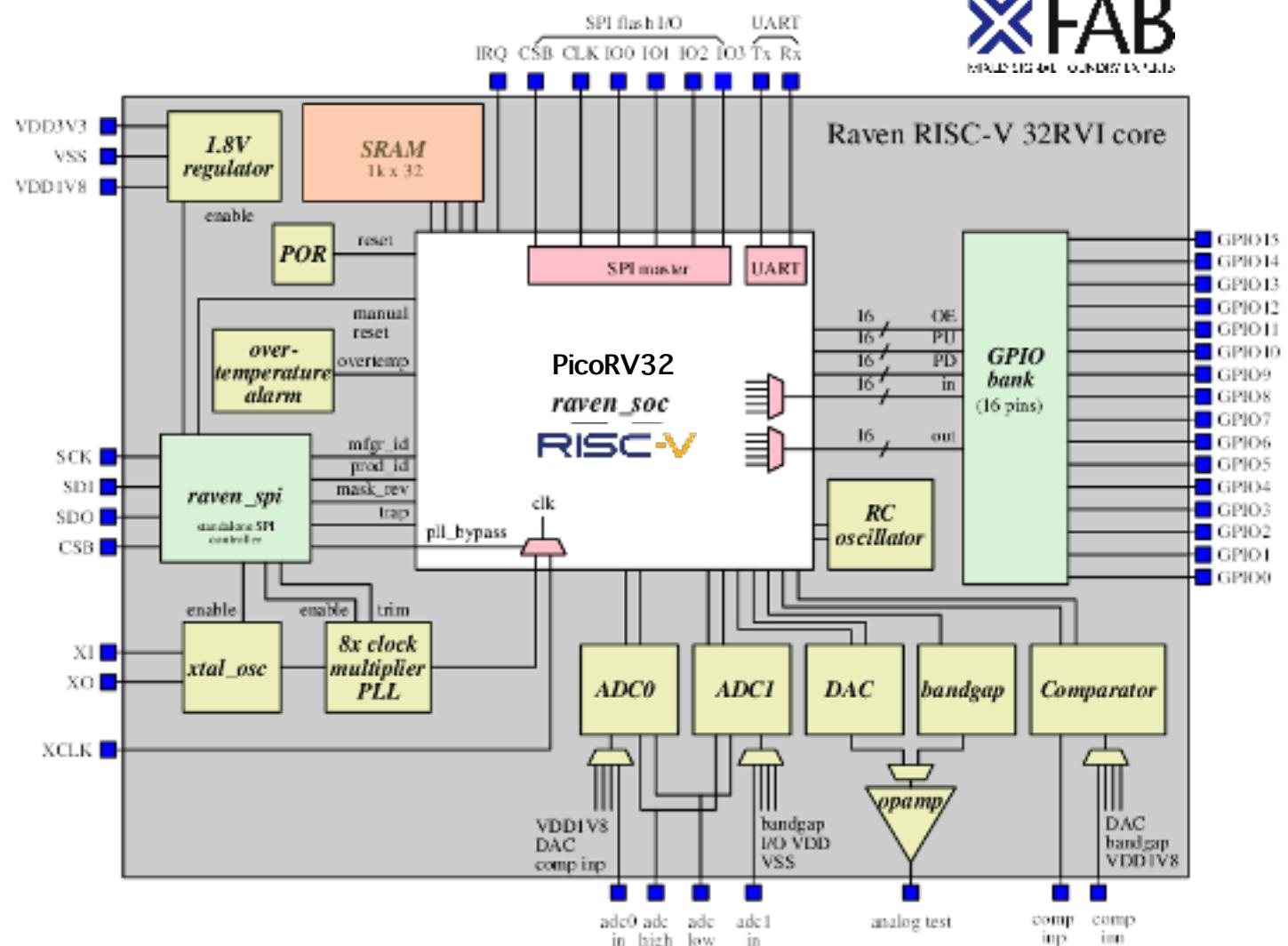
# **EFABLESS SoC's**

# RAVEN - 32-bit RISC-V uC

## Key Features

- RISC-V CPU (PicoRV32)
- SRAM 32x1024
- 100 MHz clock rate
- Programmable clock source
- 16 channels GPIO
- 2 ADCs
- 1 DAC
- 1 Comparator
- Over-temperature alarm
- 100 kHz RC oscillator
- Programmable functions on GPIO outputs
- Programmable interrupts on GPIO inputs

<http://github.com/efabless/raven-picrv32>



RAVEN  
nticati

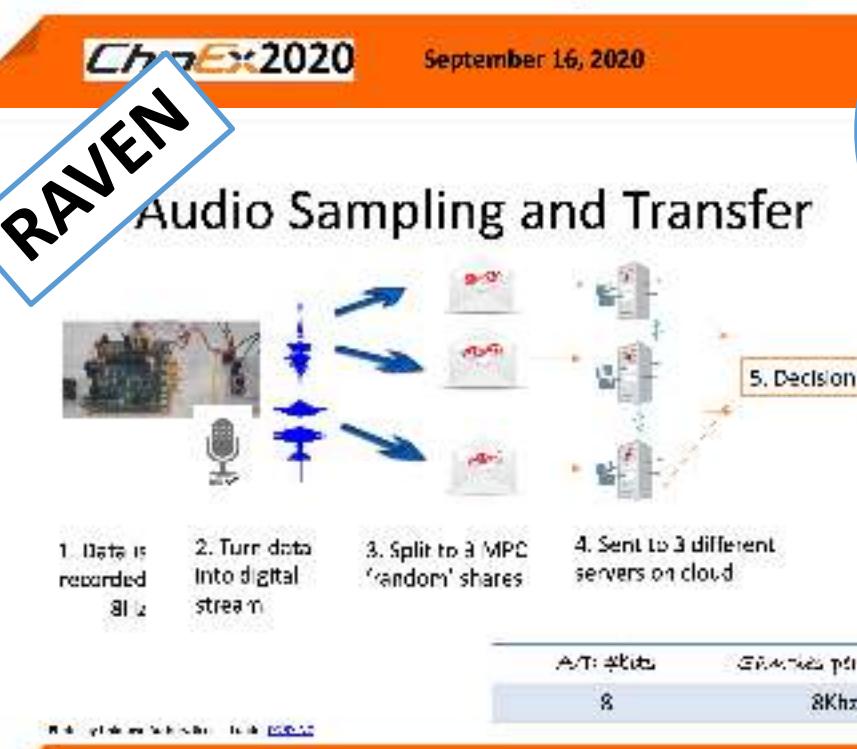
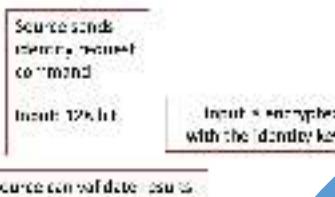
## AES Authentication

Authentication / Identification / Signature

✓ Confirming the user is who or what is stated

- chip encrypts data with an ‘identity key’
  - Key is symmetric

- R-PI have authentication requests verified by the Raven processors externally



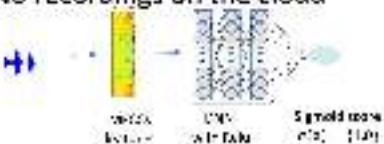
**For more information about Raven & Ravenna**  
[https://efabless.com/design\\_catalog](https://efabless.com/design_catalog)

## Audio Sampling and Transfer

Wave voice detection

Private keyword recognition

- Keyword is located in the recording
  - No recordings on the cloud

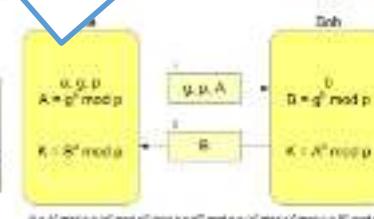


- sMPC random shares are just random numbers



PKI Implementation

- ▶ Demo:
    - Standard key exchange Diffie-Hellman
    - Compute public and private keys
    - Ravenna chips



RAVENNA

# RAVENNA - 32-bit RISC-V uC

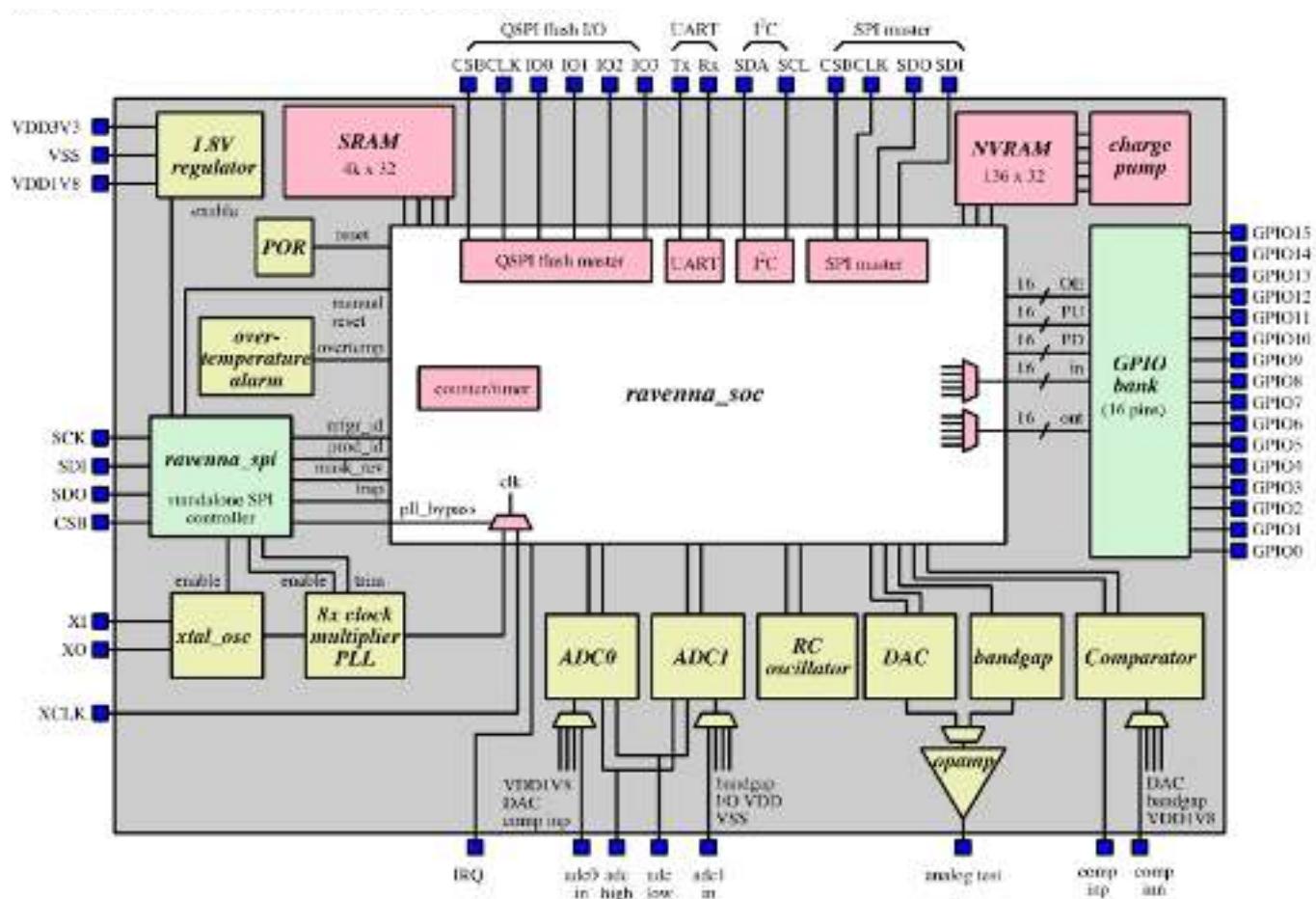
## Features:

The SoC design incorporates on-board analog functions, including the following:

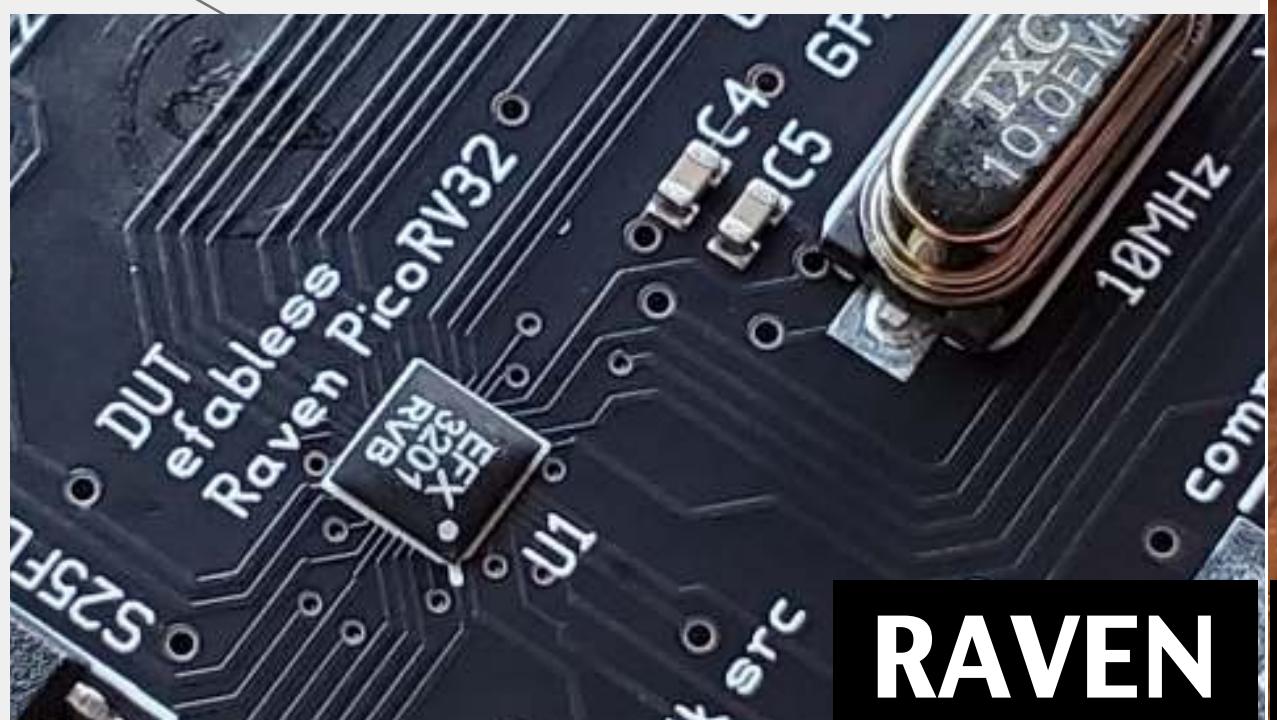
- 2 10-bit SAR ADCs
- 1 10-bit DAC
- 1 analog comparator
- 1 100kHz RC oscillator
- 1 1.235V band gap reference 1 high temperature alarm

Digital functions/features of the SoC include:

- 1 QSPI flash controller 1 UART
- 1 SPI master
- 1 I<sup>2</sup>C master
- 1 counter-timer
- 16 general-purpose digital input/output channels
- 4k word (4096 bytes × 32 bits) on-board SRAM
- 136 (128) word (128 bytes × 32 bits) on-board NVRAM



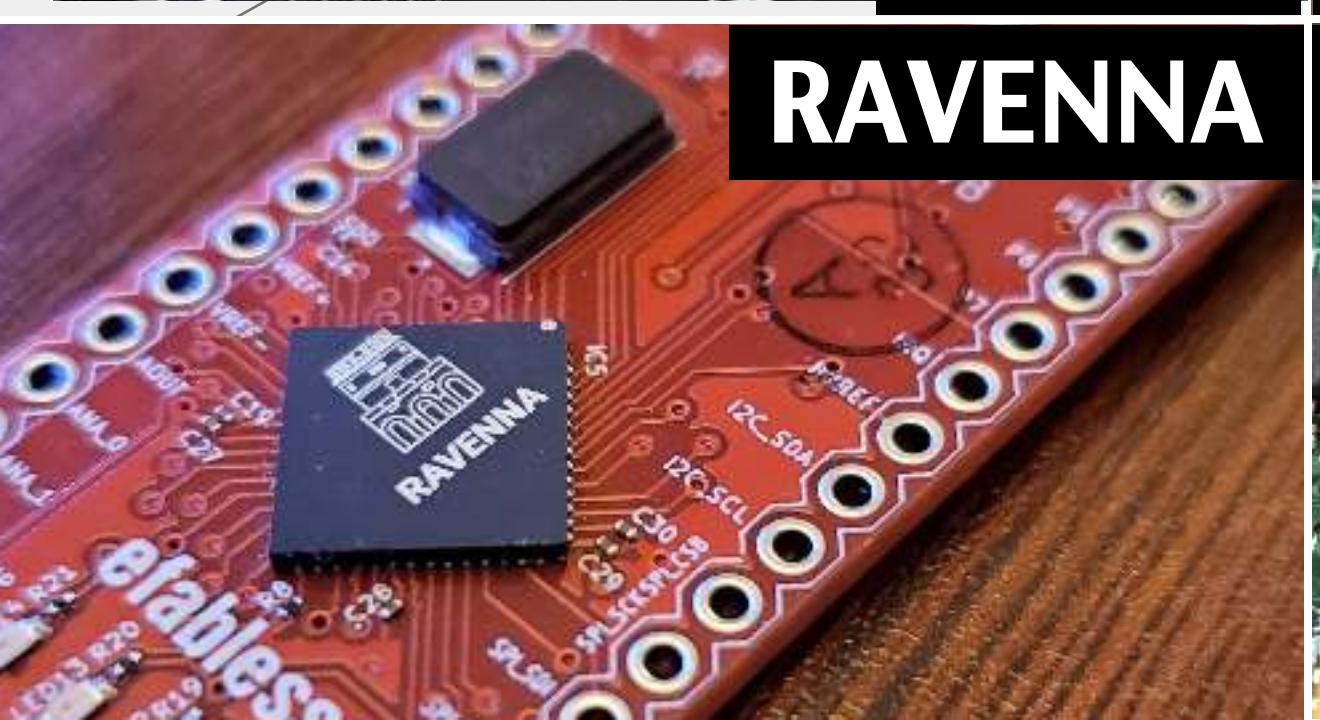
Ravenna PicoRV32 SoC die (2.573mm × 2.068mm)



RAVEN



RAPTOR



RAVENNA



HYDRA

# PARTNERS AND CUSTOMERS

## Customers



## Ecosystem Partners



# Open Silicon Prototyping Program



# CONTINUOUS INTEGRATION OF IC'S (CIIC)



# SkyWater-PDK Released

June 30, 2020



[github.com/google/skywater-pdk](https://github.com/google/skywater-pdk)

No NDA, nothing to sign^, just clone  
and run: *make timing*

[google / skywater-pdk](https://github.com/google/skywater-pdk)

Unwatch ▾

115

Unstar

1.2k

Fork

114

The more we all support it the more it happens

Well ....

What can I do with the  
130nm process?



# Intel Chips



13  
**2000**  
**Intel® Pentium® 4 processor**

Initial clock speed:  
1.5GHz  
Transistors:  
42 million  
Manufacturing technology:  
0.18 micron

14  
**2001**  
**Intel® Xeon® processor**

Initial clock speed:  
1.7GHz  
Transistors:  
42 million  
Manufacturing technology:  
0.18 micron

15  
**2003**  
**Intel® Pentium® M processor**

Initial clock speed:  
1.7GHz  
Transistors:  
55 million  
Manufacturing technology:  
90nm

16  
**2006**  
**Intel® Core™2 Duo processor**

Initial clock speed:  
2.66GHz  
Transistors:  
291 million  
Manufacturing technology:  
65nm

410 million  
Manufacturing technology:  
45nm

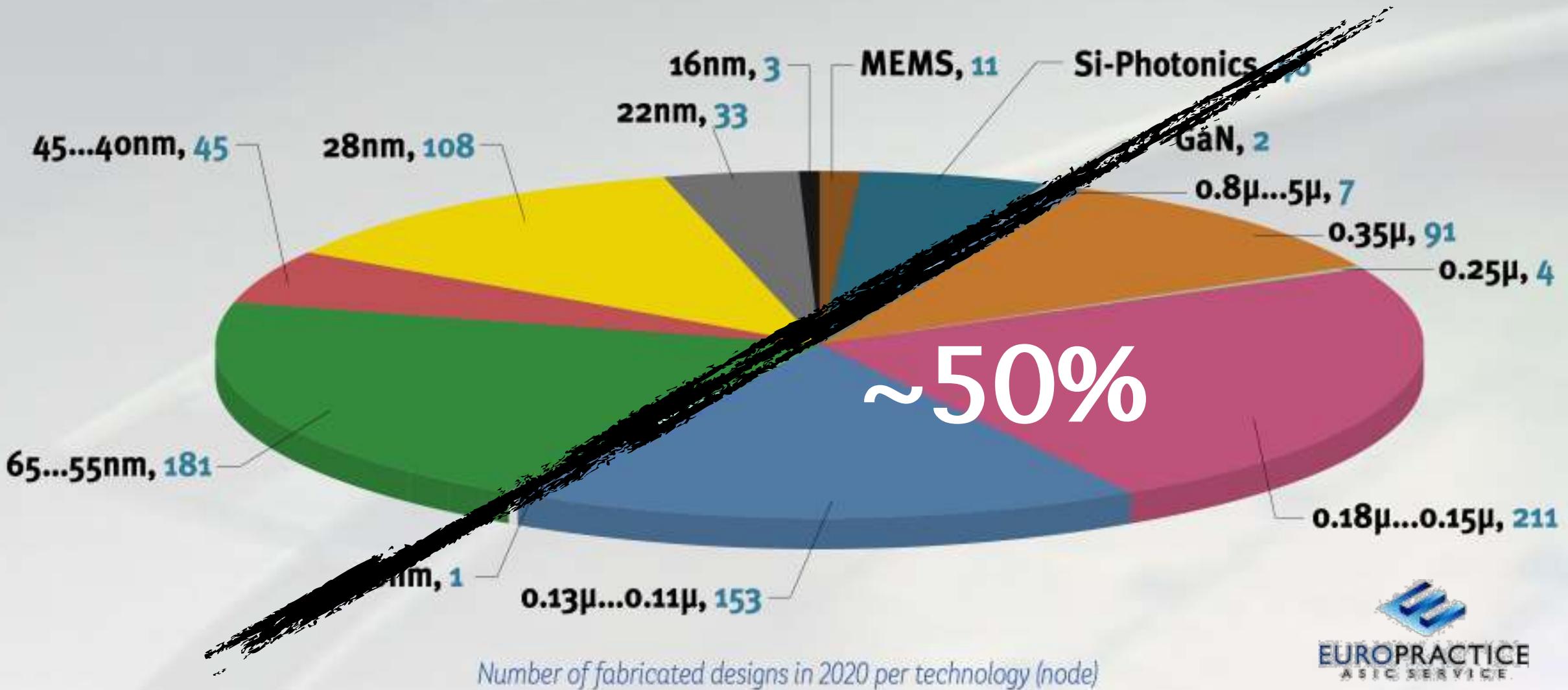
47 million  
Manufacturing technology:  
45nm

1.16 billion  
Manufacturing technology:  
32nm

1.4 billion  
Manufacturing technology:  
22nm



# WE SHOULD WORK ON ALL PROCESSES



# FOSSI DIALUP SERIES



**FOSSI**  
Foundation

[youtube.com/c/FOSSiFoundation/videos](https://youtube.com/c/FOSSiFoundation/videos)

Tim Ansell - Fully open source manufacturable PDK for a 130nm process

The [SkyWater Open Source Process Design Kit \(PDK\)](#) is a joint project of Google and SkyWater Technology Foundry to provide a fully open source PDK.

In this event, Tim Ansell will outline the collaboration and the goals of the project. He will get into the technical details of the PDK and outline the roadmap of the project..



[j.mp/du20-pdk](https://j.mp/du20-pdk)

**OpenROAD**

**OpenLANE**  
Fully automated FOSS RTL to GDSII based on OpenROAD

Mohamed Shalan

Tuesday, July 28, 2020  
16:00 GMT



[j.mp/du20-openlane](https://j.mp/du20-openlane)

 **striVe SoC Family**

Mohamed Kassem

Tuesday, August 25, 2020  
16:00 GMT



[j.mp/du20-strive](https://j.mp/du20-strive)

  
**Designing new cells for SkyWater 130nm**

James Stine

Tuesday, September 22, 2020  
16:00 GMT



[j.mp/du20-stdcells](https://j.mp/du20-stdcells)

  
**OpenRAM**

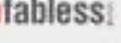
**OpenRAM on SkyWater 130nm**

Matt Gutheus

Tuesday, October 20, 2020  
16:00 GMT



[j.mp/du20-openram](https://j.mp/du20-openram)

  
**Magic VLSI Layout Tool**

**Magic for DRC checks on SkyWater 130nm**

Tim Edwards

Tuesday, November 17, 2020  
16:00 GMT

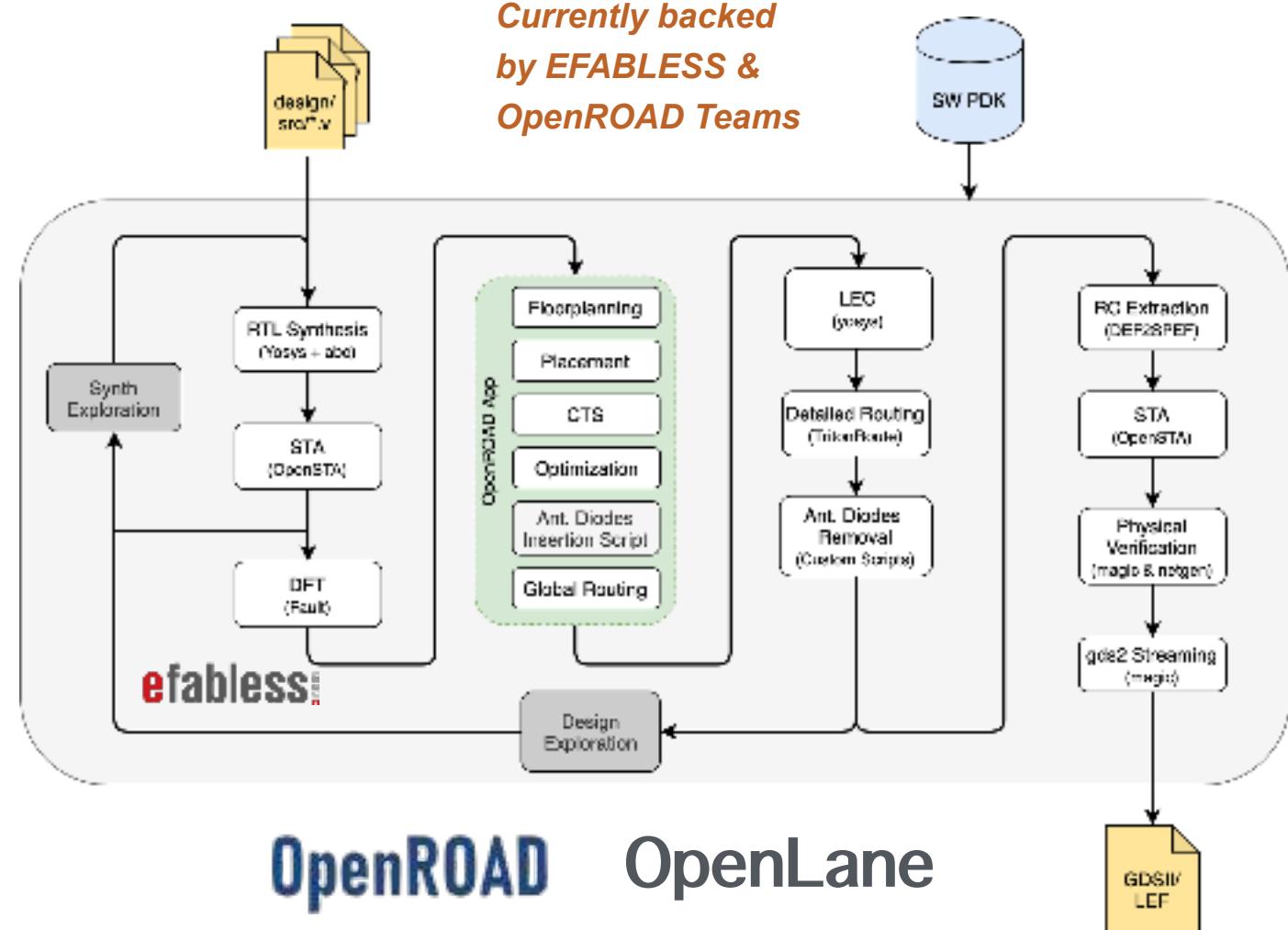


[j.mp/du20-magic](https://j.mp/du20-magic)

# COMPILER-LIKE RTL2GDS

OpenLane is a no-human in the loop  
RTL to GDS compiler built around  
OpenROAD that works like a **GNU  
software compiler with trade-offs  
in area and performance.**

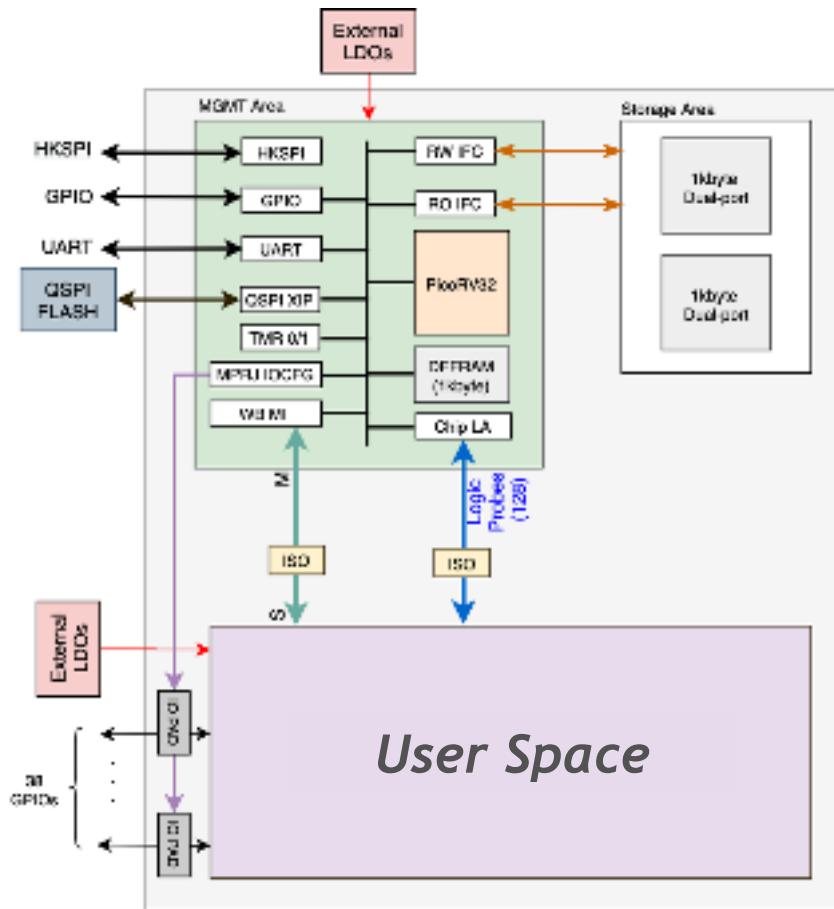
It opens the door for software  
developers to generate hardware  
representation without the need for  
details. That's at least a **1000X** more  
potential designers!



Supports SKY130, GF130, XFAB180

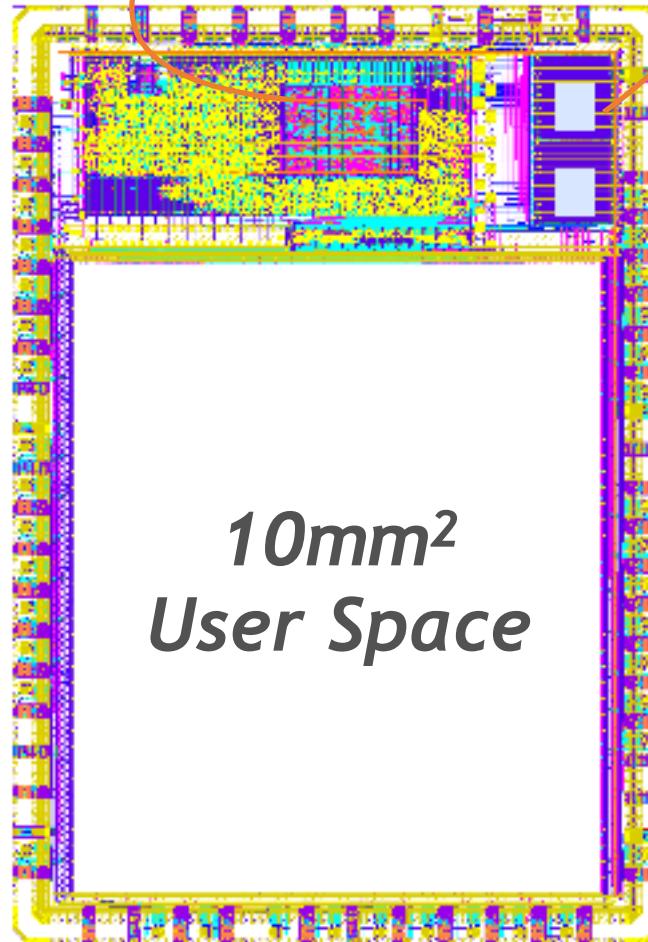
12nm support is under development by OpenROAD team

# CARAVEL HARNESS



<https://github.com/efabless/caravel>

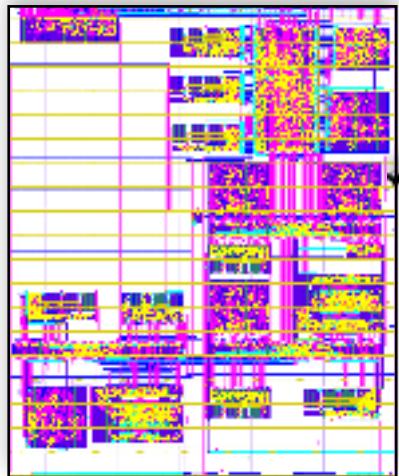
PicoRV32 OpenRAM  
OpenROAD OpenLane



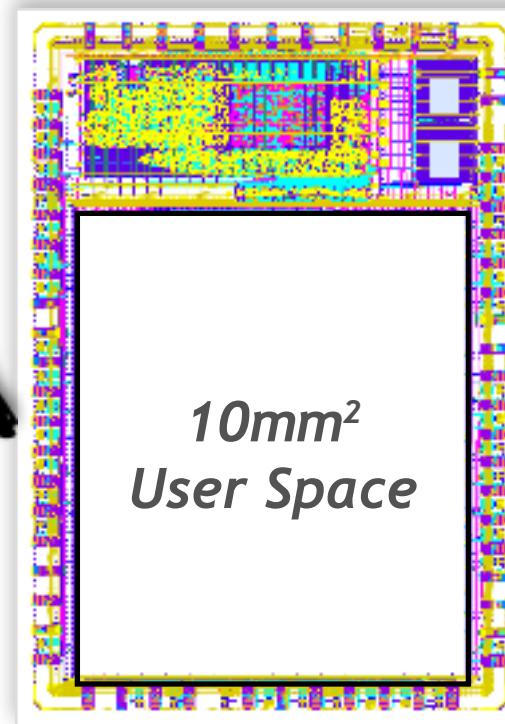
CARAVEL Platform

github/workflows
.travisCI
def
docs
gds
irsim
lef
lv
macros
msg
maglef
ngspice
oss
openlane
qflow
scripts
signoff
spif
spiflash
utils
verilog
xvce

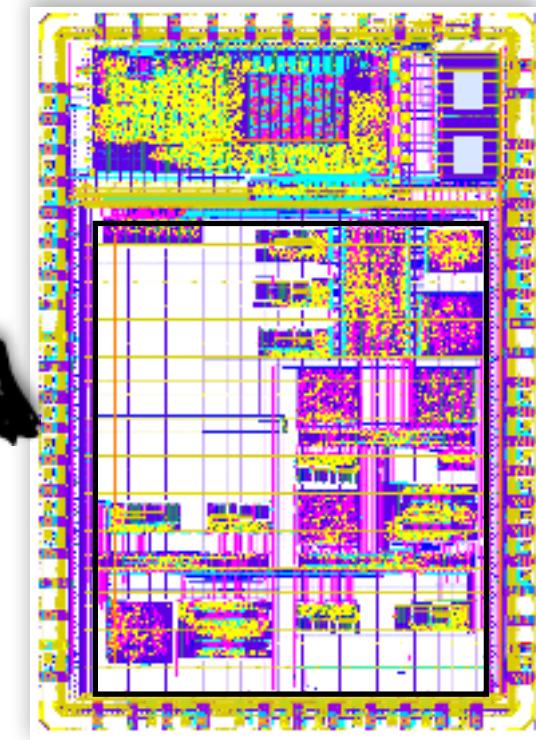
# CARAVEL HARNESS - HOW IT'S USED



USER DESIGN



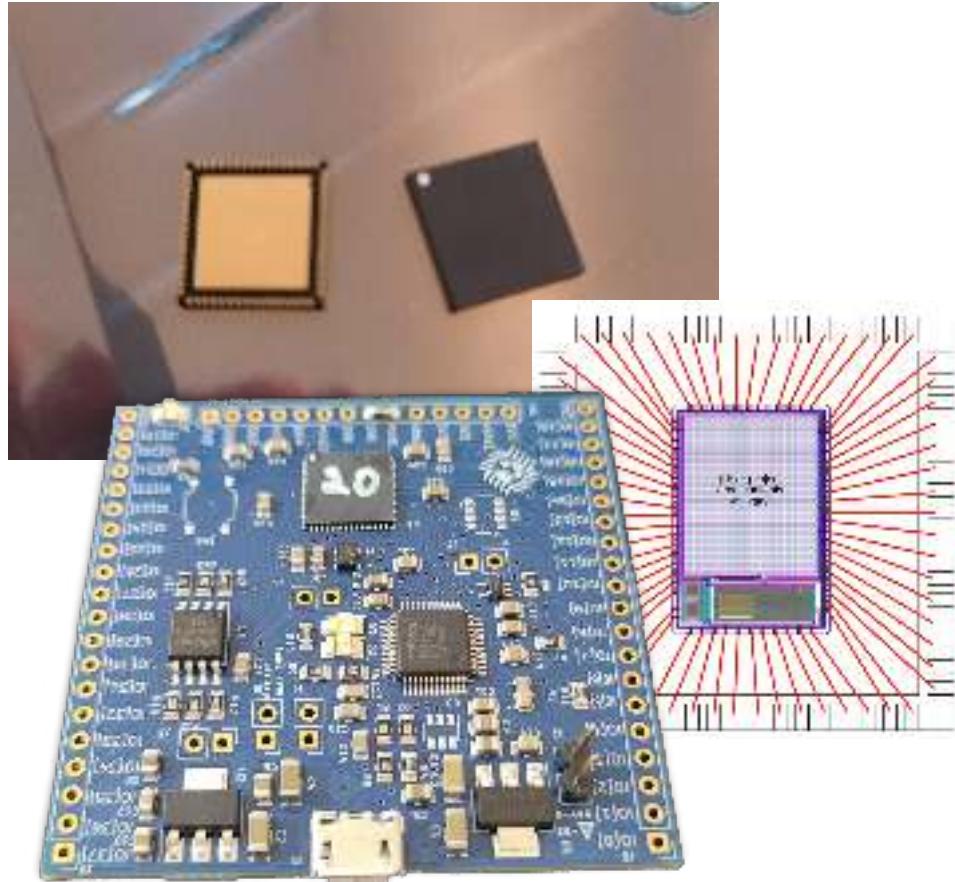
CARAVEL



CARAVEL

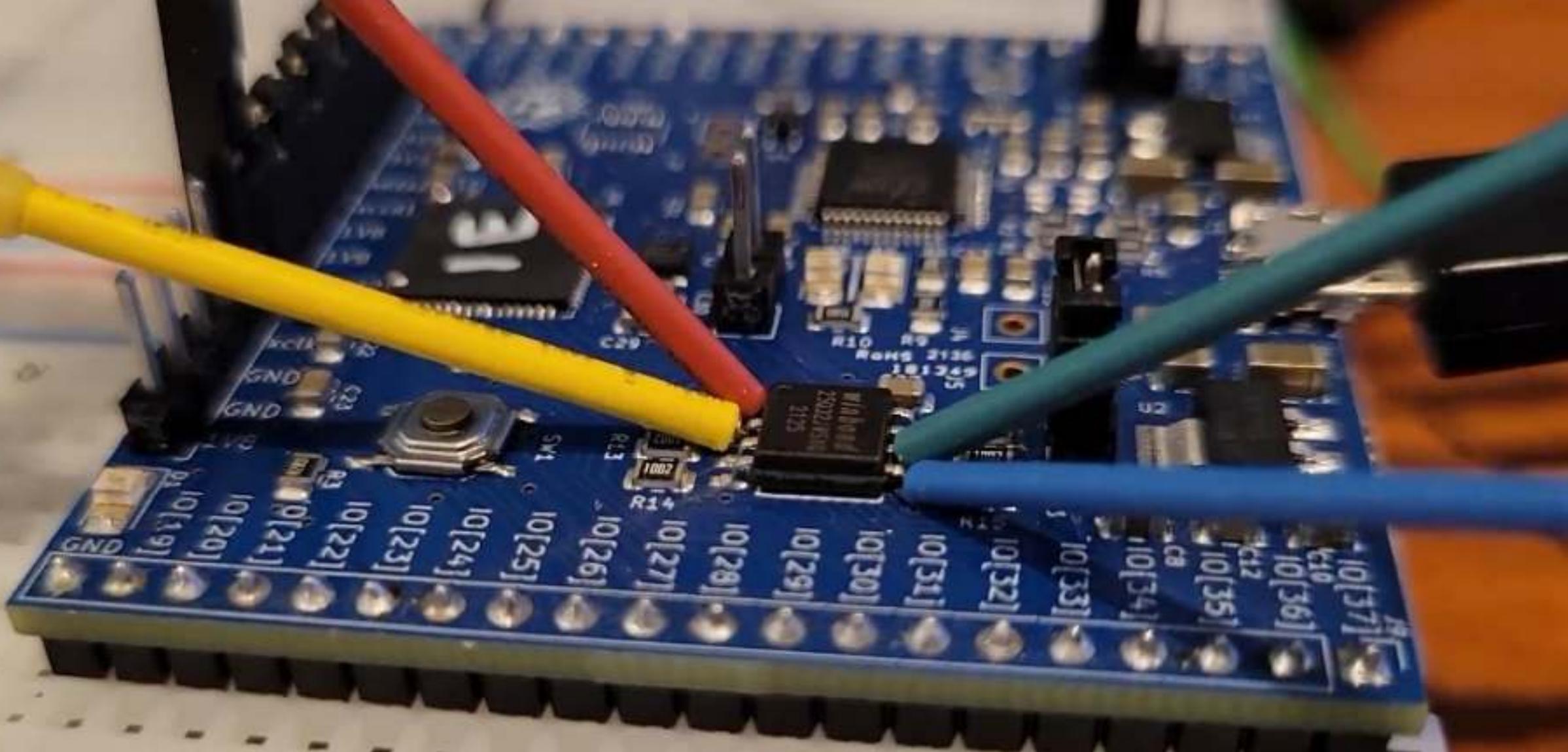
<https://github.com/efabless/caravel>

# SILICON VALIDATION



Actual Chip and Board Images

- Users receive **packaged chips** as well as **assembled 5 evaluation boards** with their projects
- An open-source software test framework is available for the program including
  - Logic Analyzer
  - Drivers for common peripherals
  - Flash programming utility
  - Example firmware routine for common functions
  - Instructions for extending the test examples for your project



# ENGAGEMENT IN NUMBERS - SLACK SPACE

2,000+

COMMUNITY  
MEMBERS

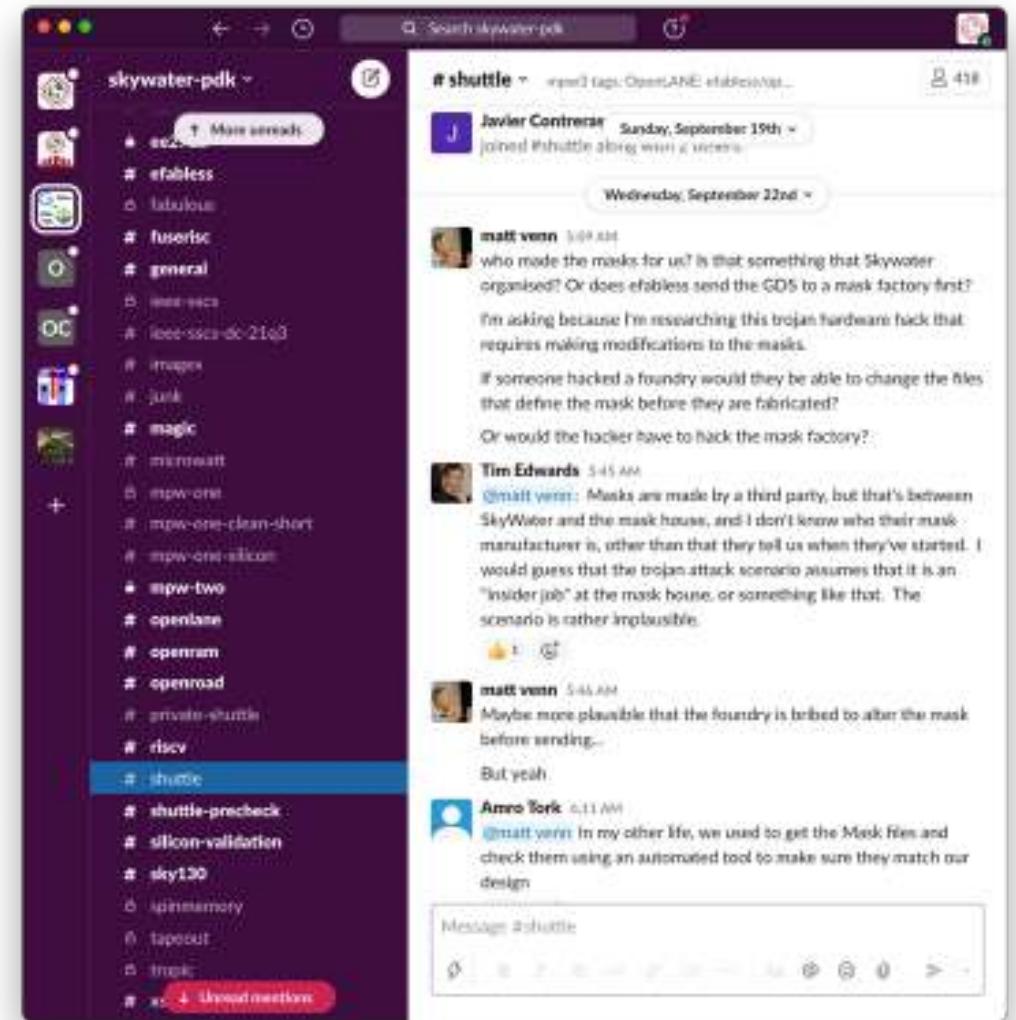
100+

CHANNELS  
& TOPICS

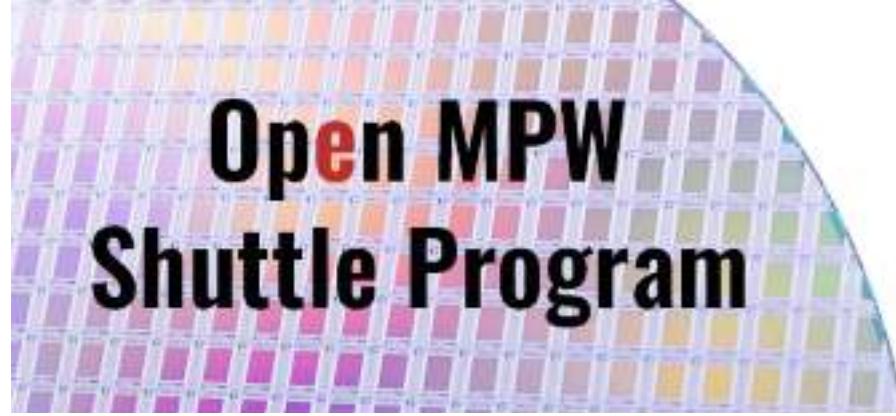
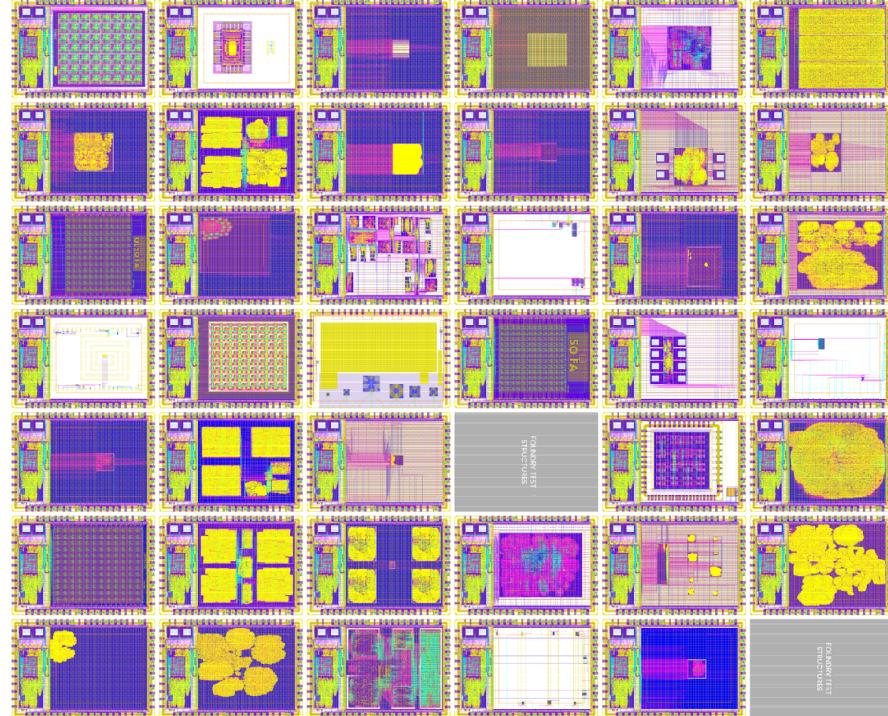
Join SkyWater-PDK

Community

<https://join.skywater.tools>



The first shuttle was overbooked: **45** designs submitted in **30 days!**

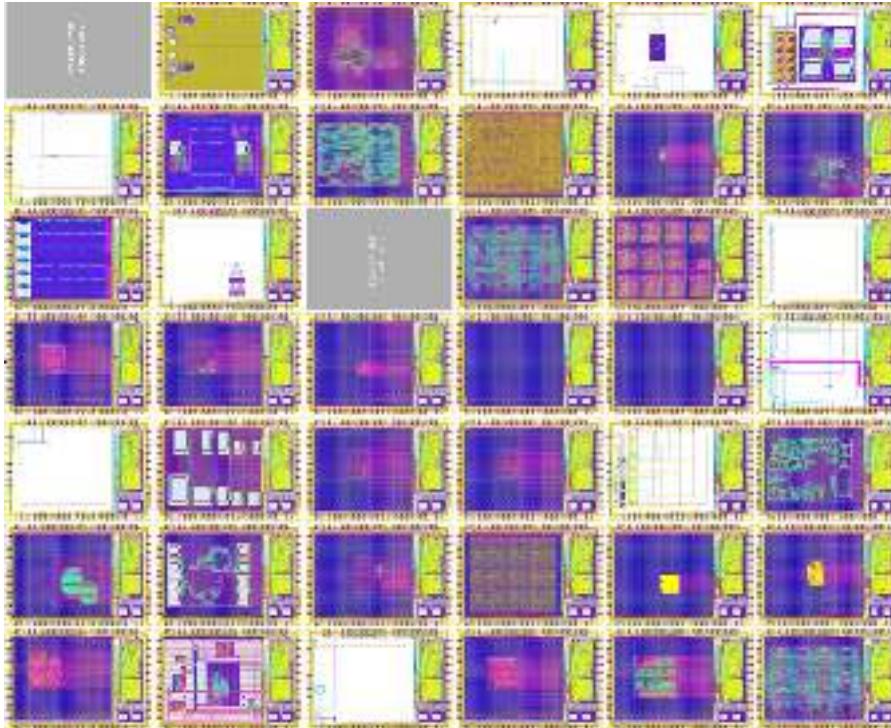


## DESIGN TYPES - MPW ONE

- 9 x Open processor cores
- 9 x SoC's
- Crypto-currency Miner
- Robotic App Processor
- Amateur Satellite Radio Transceiver
- 7 x Analog/RF
- 5 eFPGA's

*All designs  
must be Open  
Source*

And so was the second: **56** designs submitted in **30 days!**



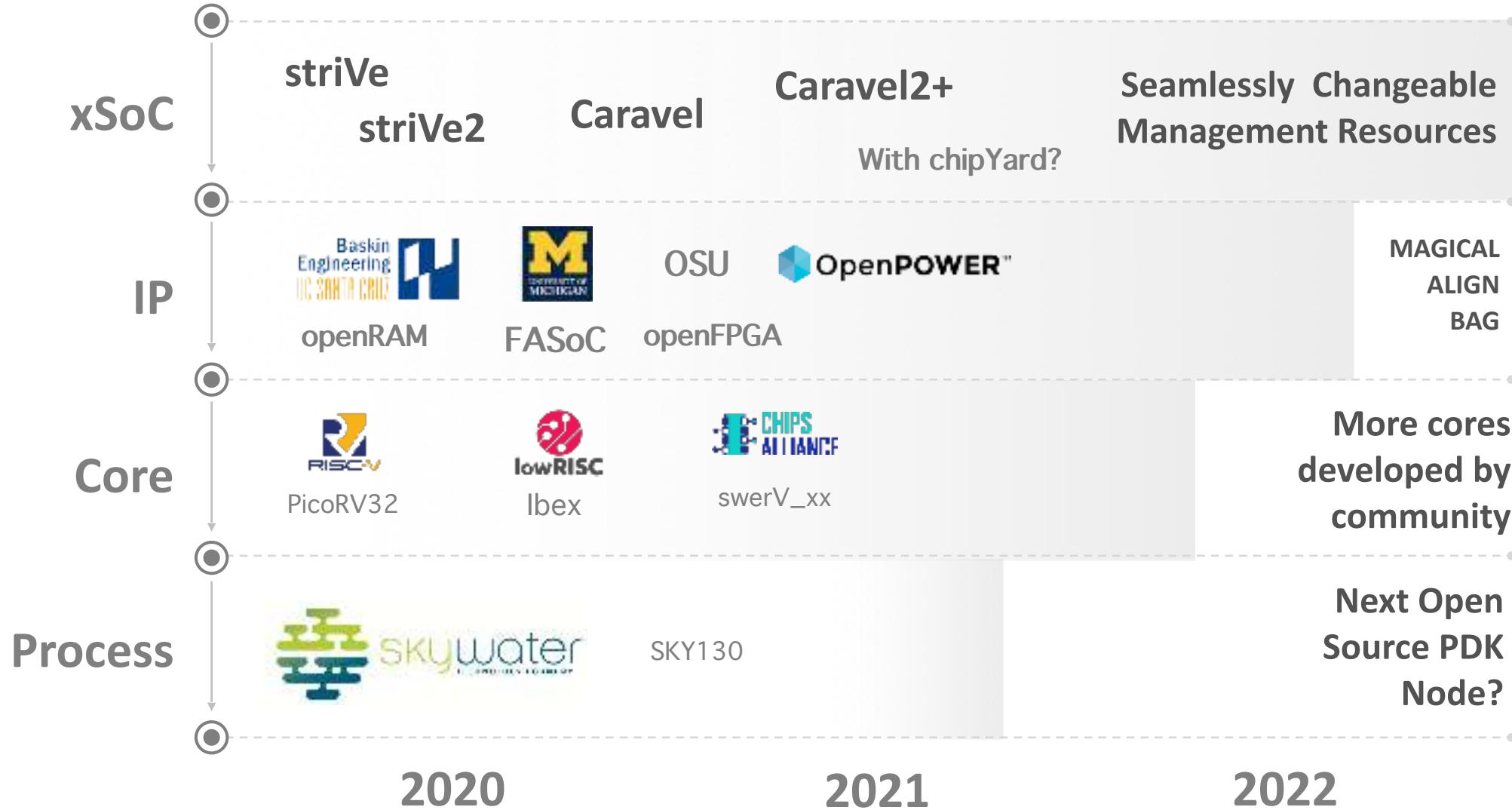
**efabless**.com  
Sponsored by  
**Google**

## DESIGN TYPES - MPW TWO

- 11 x Open processor cores
- 11 x SoC's
- Crypto-router
- Time to Digital Converter - LIDAR
- Multi-project harness for Caravel x 16
- 17 x Analog/RF
- 2 eFPGA's

*All designs  
must be Open  
Source*

# KEEP MOVING - MORE IS COMING



# BUT ....

What if do not want to open source my design?

I would like to book & guarantee my spot!

I seriously care about the schedule.

# chipIgnite



## Includes:

- Complete EDA design flow
- Automated physical implementation for digital designs
- 37 programmable IOs supporting digital and analog
- Pre-designed packaging and evaluation board
- Supports commercial EDA options as well
- QFN or WCSP packaged parts based on shuttle
- 10 mm<sup>2</sup> user design area
- 5 evaluation board assemblies
- 100, 300 or 1000 packaged parts

## Schedule:

Shuttle	Tapeout	Delivery	Parts
MPW-Q2106	June 18, 2021	October 6, 2021	100 QFN
MPW-C210	October 15, 2021	January 31, 2022	300 or 1000 WCSP

Note: Schedule depends on meeting minimum project capacity  
\$200 reservation fee (fully refundable if minimum projects not met)

## Evolve your Design Idea

1

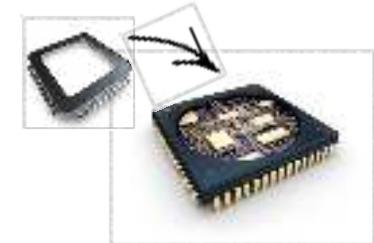
- Explore/what-if/trade-offs
- Simulate, verify, iterate
- Design, verify, modify layout
- Collaborate, brainstorm with others



## Design-Ship ToolBox

2

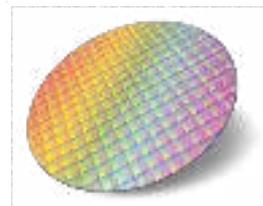
- Carrier SoC Harness
- Predesigned ESD Protection
- WCSP Packaged
- Starter IP design library



## Send to Manufacturing

3

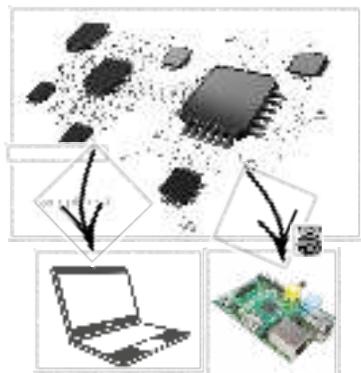
- Multiple foundry partners
- Multiple process options
- Unprecedented die area cost/mm
- Get samples + dev boards by mail



## Validate your Design

4

- Get a well-equipped tester board
- 16 Analog/32 Digital Channels
- Standard Test description language
- Laptop or Raspberry Pi driven
- Correlate with pre-silicon sims



**efabless**.com

# chipIgnite

Rapid IC Creation

**\$9,750**  
per project

## Chip Design Made Easy

chipIgnite provides you with a pre-designed carrier-chip along with automated open-source design flow making your own chip easy and affordable

- Rapid design implementation leveraging an automated digital design flow and full chip template
- Prototype and early volume fabrication for the SKY130 open PDK
- Two pricing options:
  - \$9,750 for 100 QFN or 300 W CSP parts
  - 1000 parts for \$20 each
- Private shuttle: no open-source requirement
- Guaranteed reservation with \$200 deposit

**skywater** INTEGRATED CIRCUITS

# chipIgnite

- 1) No open source requirement
- 2) Guaranteed space on shuttles

Large and rapidly growing demand in US and overseas

Initial focus on education and research

# chipIgnite

customers since June 2021

1 Stanford EE272 Design course  
*Three additional universities & one startup running projects*

Pipeline is building



2

SSCS “PICO” Open Source Design Contest:

**56+** submitted designs

**10** will tape out at Efabless



Open Source  
FPGA Foundation  
global program  
innovation among  
university  
students

3

**2** ChipIgnite Slots per University

Turkey, Pakistan, India, Australia

**efabless**  
efabless.com

# chipIgnite

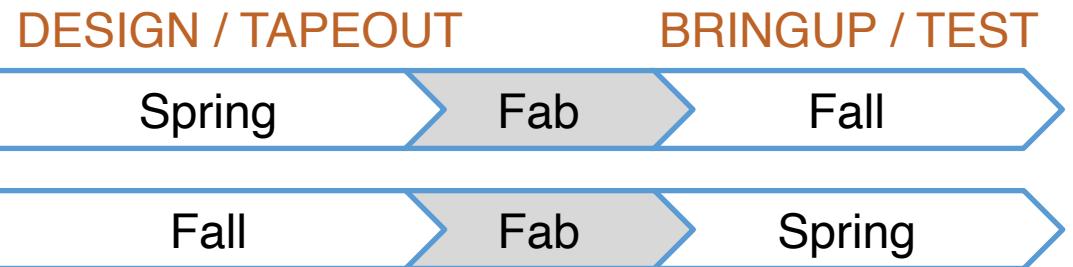
## FOR UNIVERSITIES

Undergraduate courses  
Capstone projects  
Graduate Research



## TAPE-OUT COURSES

- Analog and / or Digital Design Courses
- Two-session courses:



- Single session courses:
  - Design + test via FPGA
  - Design + test previous student project
  - Test broken design + fix and tapeout
  - Future: one course period design/tape-out/test

# EFABLESS FOR WORKFORCE DEVELOPMENT

efabless all-in-one platform makes it possible to engage 1000's of students at any stage of education in real life learning experience in design, verification, prototyping and validation of microelectronics

# WORKFORCE DEVELOPMENT AT A GLANCE

Audience	Goal	Complexity	Cost	Scale	Commercial Applicability	Requirements
High School	More Interest	LOW	LOW	100,000's	LOW	Mature nodes, open-source
Undergraduate	Expertise	MEDIUM	MEDIUM	10,000's	SELECTED	Mid-nodes, open-source + commercial
Graduates	Adv. Expertise Novel IP	HIGH	HIGH	1000's	HIGH	Advanced nodes, commercial tools

# CALL TO - ACTION

It is a massive undertaking we should work together

Repeat good examples

Apple awarded innovation grants to engineering schools at four **historically black colleges and universities** to expand their coursework, scholarships, and internship opportunities in hardware engineering and silicon chip design.

**Thank you!**

# Get Involved - Useful Links / Repos

## Information Hub

[github.com/efabless/skywater-pdk-central](https://github.com/efabless/skywater-pdk-central)

- Join SkyWater PDK Slack Space - <https://join.skywater.tools>
- The OpenLane flow for digital PnR can be found at <https://openlane.io>
- The OpenROAD Project <https://theopenroadproject.org/>
- The documentation is at <https://docs.skywater.tools>
- MPW-ONE [https://efabless.com/open\\_mpw\\_shuttle\\_project\\_mpw\\_one](https://efabless.com/open_mpw_shuttle_project_mpw_one)
- Caravel documentation <https://caravel-harness.readthedocs.io/en/develop/index.html>
- WOSET/ICCAD Workshop on EDA <https://woset-workshop.github.io/WOSET2020.html>